Intel® Xeon™ Processor DP

Thermal Design Guidelines

January 2003

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Revision History

Rev.	Description	Date
-003	Added updated information for Intel® Xeon™ processor with 512 KB L2 cache and Intel Xeon processor with 533 MHz system bus.	December 2002
-002	Added information for Intel® Xeon™ processor with 512 KB L2 cache. Integrated thermal solution functional specifications into document (previously a separate document).	January 2002
-001	Initial Release	May 2001

1 Introduction

In a system environment, the processor's temperature is a function of both the system and component thermal characteristics. The system level thermal constraints consist of the local-ambient temperature at the processor and the airflow over the processor(s) as well as the physical constraints at and above the processor(s). The processor temperature depends on the component power dissipation, size and material (effective thermal conductivity) of the integrated heat spreader; attach mechanism and the presence of a thermal cooling solution.

The continued push of technology is providing an increase in performance levels (higher operating speeds, GHz) and packaging density (more transistors). This push also increases the challenge of system thermal design. As operating frequencies increase and packaging size decreases, the power density increases and the demand on thermal cooling and system airflow increases. The result is an increased importance on system design to ensure that thermal design requirements are met for each component in the system.

The information on thermal design provided in this document is for reference only, and suggests good thermal design practices. All responsibility for determining the adequacy of any thermal or system design remains solely with the reader. Intel makes no warranties or representations that merely following all of the instructions presented in this document will result in a system with adequate thermal performance. Please refer to the terms on page 2 of this document for the detailed written disclaimer.

1.1 Document Goals

The thermal power level and thermal power density of this processor generation are higher than previous Intel architecture processors. Depending on the type of system and the chassis characteristics, new system designs may be required to provide adequate cooling for the processor. The goal of this document is to provide an understanding of these thermal characteristics and discuss guidelines for meeting the thermal requirements imposed on single and multiple processor systems. Guidelines specific to the processor are presented in the body of this document. More general guidelines for thermal design can be found in Appendix A.

1.2 Document Scope

This document discusses thermal management and measurement techniques for the Intel® Xeon™ processors (including the Intel Xeon processor with 256-KB L2 cache, the Intel Xeon processor with 512-KB L2 cache and the Intel Xeon processor with 533 MHz system bus) which are primarily intended for server and workstation applications. It will also address the issues of the integrated thermal management logic and its impact on thermal design. Unless otherwise noted, references to "processor" throughout this document apply to the dual processor (DP) version of the Intel Xeon processors.

The physical dimensions and power numbers used in this document are for reference only. Please refer to the processor datasheet for the product dimensions, thermal design power dissipation, and maximum case temperature. In case of conflict in data, the information in the datasheet supercedes any data in this document.

1.3 References

- *Intel® Xeon™ Processor at 1.40 GHz, 1.50 GHz. 1.70 GHz and 2.0 GHz Datasheet*[1]
- *Intel® Xeon™ Processor with 512-KB L2 Cache at 1.80 GHz to 2.80 GHz Datasheet*[1]
- *Intel® Xeon™ Processor with 533 MHz System Bus at 2 GHz to 2.80 GHz Datasheet*[1]
- *Intel® Xeon™ Processor and Intel® 860 Chipset Platform Design Guidelines*[1]
- *Intel® Xeon™ Processor Enabled Components Mechanical Models in ProE* Format*[1]
- *Intel® Xeon™ Processor Enabled Components Mechanical Models in IGES Format*[1]
- *Intel® Xeon™ Processor Thermal Models in Flotherm* and IcePak* Formats*[1]
- *Intel® Xeon™ Processor with 512 KB L2 Cache Thermal Models in Flotherm* and IcePak* Formats*[1]
- Intel® Xeon™ Processor with 512 KB L2 Cache Processor Mechanical Models in ProE* and IGES Formats[1]
- *Intel® NetBurst™ Microarchitecture BIOS Writer's Guide*[2]
- *603-Pin Socket Design Guidelines*[1]
- *Guidelines for Duct Design for Dual Processor Platform Applications2*
- *SSI Entry-Level Electronics Bay Specification*[3]
- *SSI Mid-Range Electronics Bay Specification3*
- *SSI High-End Electronics Bay Specification3*
- *European Blue Angel Recycling Standards*

1.4 Definition of Terms

- ACPI – Advanced Configuration and Power Interface (see http://www.teleport.com/~acpi/).
- Bypass/no-bypass – Bypass is the area between a heatsink and any object that can act to form a duct. For this example it can be expressed as a dimension away from the outside dimension of the fins to the nearest surface.
- P_{MAX} – the maximum processor power, as specified in the processor's datasheet.
- T_{LA} ($T_{LOCAL-AMBIENT}$) – the measured ambient temperature locally surrounding the processor. The ambient temperature should be measured just "upstream" of a passive heatsink, or at the fan inlet for an active heatsink.

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[1] This document is available at http://developer.intel.com.

[2] Contact your Intel Field Sales representative for ordering information.

[3] This document is available at http://www.ssiforum.org.

- $T_{AMBIENT\text{-}OEM}$ – the target worst-case ambient temperature at a given external system location as defined by the system designer (OEM).

- $T_{AMBIENT\text{-}EXTERNAL}$ – the measured ambient temperature at the OEM defined external system location.

- $T_{AMBIENT\text{-}MAX}$ – the target worst-case local-ambient temperature. To determine this, place the system in a maximum external temperature environment, and measure the ambient temperature surrounding the processor. Under these conditions, $T_{LA} = T_{AMBIENT\text{-}MAX}$.

- $T_{CASE\text{-}MAX}$ – the maximum case temperature of the processor, as specified in the processor datasheet.

- T_{CASE} – the measured case temperature of the processor.

- Thermal Monitor – The Intel Xeon processor and the Intel Xeon processor with 512 KB L2 cache implements a thermal management feature consisting of an on-die thermal diode, reference current source, comparator, external bus signal, thermal control circuit and processor registers to assist with managing thermal control of the processor. Collectively, these are referred to as Thermal Monitor.

- Thermal Control Circuit – The portion of Thermal Monitor that modulates the processor's internal clocks during an over-temperature event.

- Thermal Design Power (TDP) – A processor power dissipation target derived from profiling multiple workstation and server applications. OEMs must design thermal solutions that meet or exceed the TDP as specified in the processor datasheet.

- TIM – Thermal Interface Material – The thermally conductive compound between the heatsink and the processor case. This material fills the air gaps and voids, and enhances the spreading of the heat from the case to the heatsink.

- TBD – To be determined.

- Ψ_{CS} – The case to sink thermal resistance, which is dependent on the thermal interface material. Also referred to as θ_{TIM}.

- Ψ_{CA} – The thermal resistance between the processor's case and the ambient air. This is defined and controlled by the system thermal solution.

- U – A unit of measure used to define server rack spacing height. 1U is equal to 1.75 inches, 2U equals 3.50 inches, etc.

- Vapor Chamber – Heatsink technology similar to a heat pipe in that a liquid changes to a gaseous state to rapidly disperse the heat to a large area. A vapor chamber relies on heat spreading for thermal benefit instead of removing heat to a location away from the heatsink.

- 603-pin Socket – The surface mount Zero Insertion Force (ZIF) socket designed to accept the Intel Xeon processor and the Intel Xeon processor with 512 KB L2 cache.

2 Importance of Thermal Management

The objective of thermal management is to ensure that the temperature of all components in a system is maintained within functional limits. The functional temperature limit is the range within which the electrical circuits can be expected to meet their specified performance requirements. Operation outside the functional limit can degrade system performance, cause components to operate in a manner no longer guaranteed by their specified operation or cause component and/or system damage. Temperatures exceeding the maximum operating limits may result in irreversible changes in the operating characteristics of the component.

3 Processor Packaging Technology

The Intel Xeon processor is available in the interposer micro pin grid array (INT-mPGA) package technology while the Intel Xeon processor with 512 KB L2 cache is available in both the INT-mPGA package and the flip chip ball grid array package (FC-mPGA2). Components of the package include an integrated heat spreader (IHS), an organic land grid array (OLGA) or flip chip ball grid array (FC-BGA) package containing the processor die, and a pinned interposer. The integrated heat spreader (IHS) is designed to improve package thermal performance and is the interface for attaching a heatsink. The processor connects to the motherboard through a ZIF socket. A description of the socket can be found in the 603-pin Socket Design Guidelines.

The Intel Xeon processor uses a 31 mm [1.22 in] square OLGA core (Figure 1). The Intel Xeon processor with 512 KB L2 cache uses a 35 mm [1.38 in] square INT-mPGA core package (Figure 2) or a flip chip package (FC-mPGA2) with a 31 mm [1.22 in] IHS (Figure 3).

There is a change in total package height between the INT-mPGA and FC-mPGA2 packages that can affect heatsink retention force and thermal performance. Refer to the dimensions in the processor datasheet to determine the exact height difference and its impact to current heatsink and retention designs. Heatsink designs may require modification to accommodate the change in package height.

All processor package configurations are compatible with the 603-pin socket.

Note: In case of conflicts in dimensions, the processor datasheet supercedes this document. All dimensions are nominal values and specified in millimeters.

Figure 1. Intel® Xeon™ Processor (31 mm OLGA package)

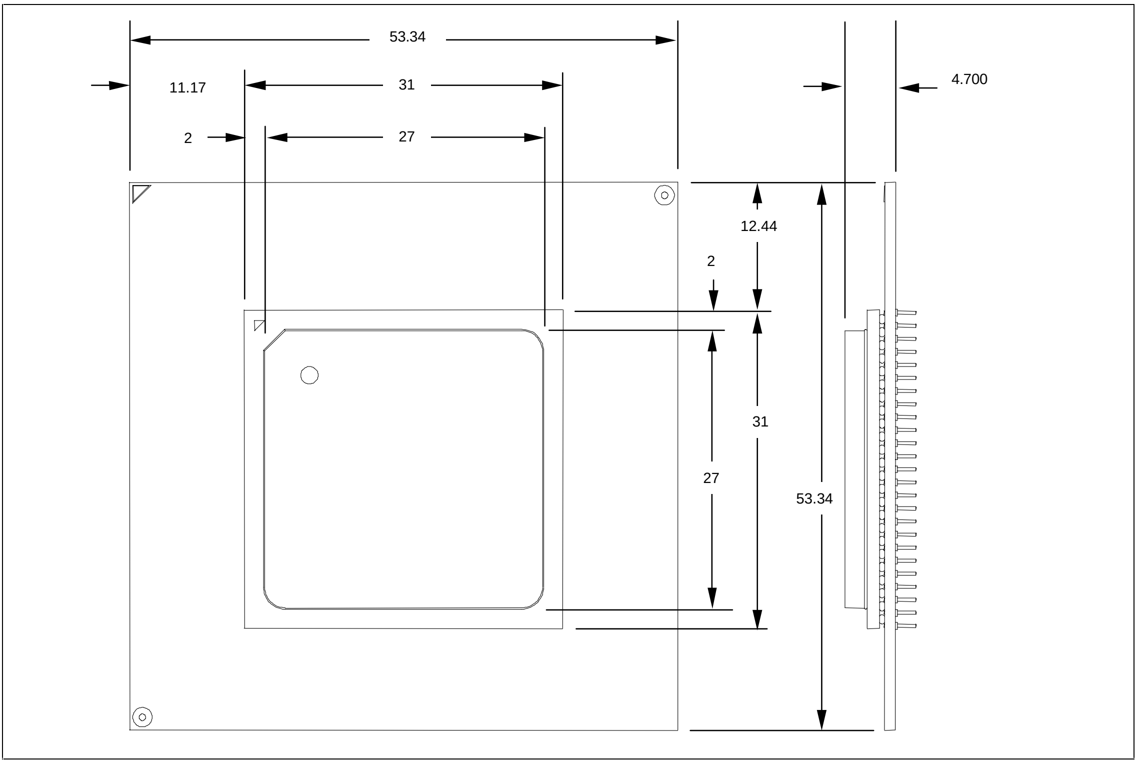


Figure 2. Intel® Xeon™ Processor with 512 KB L2 Cache Processor (35 mm INT-mPGA package)

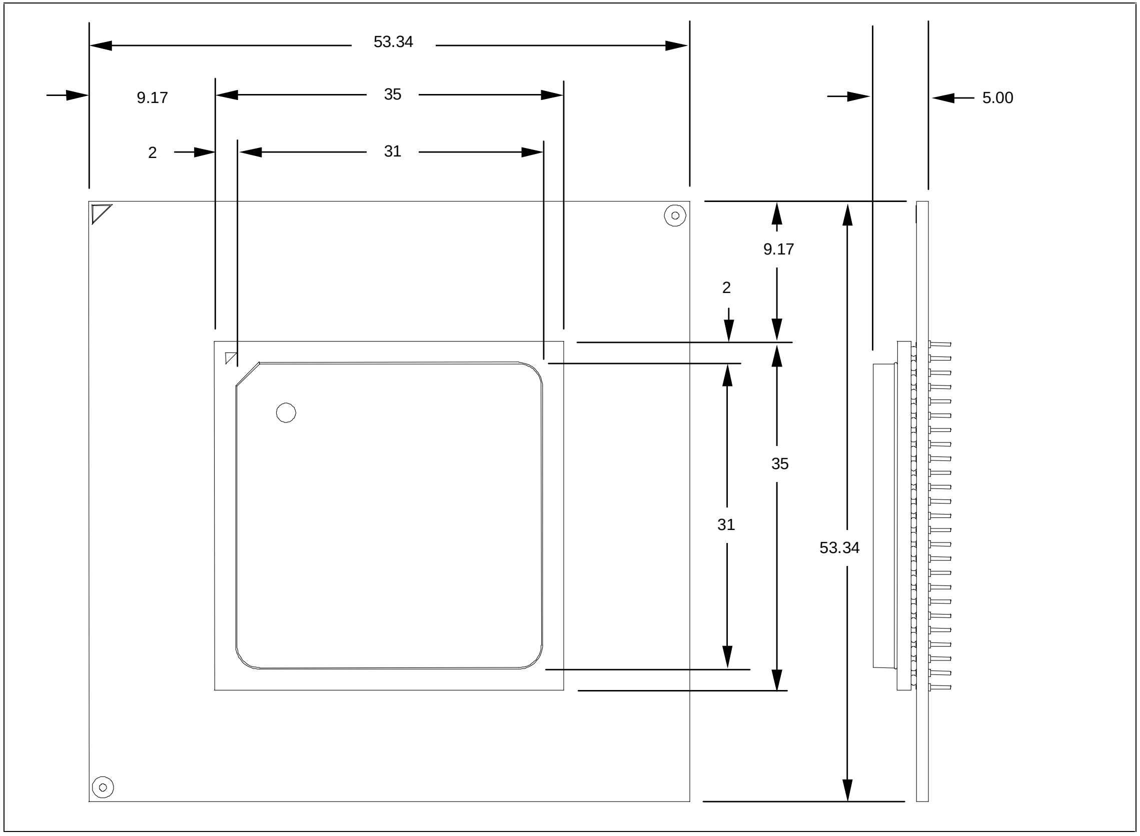
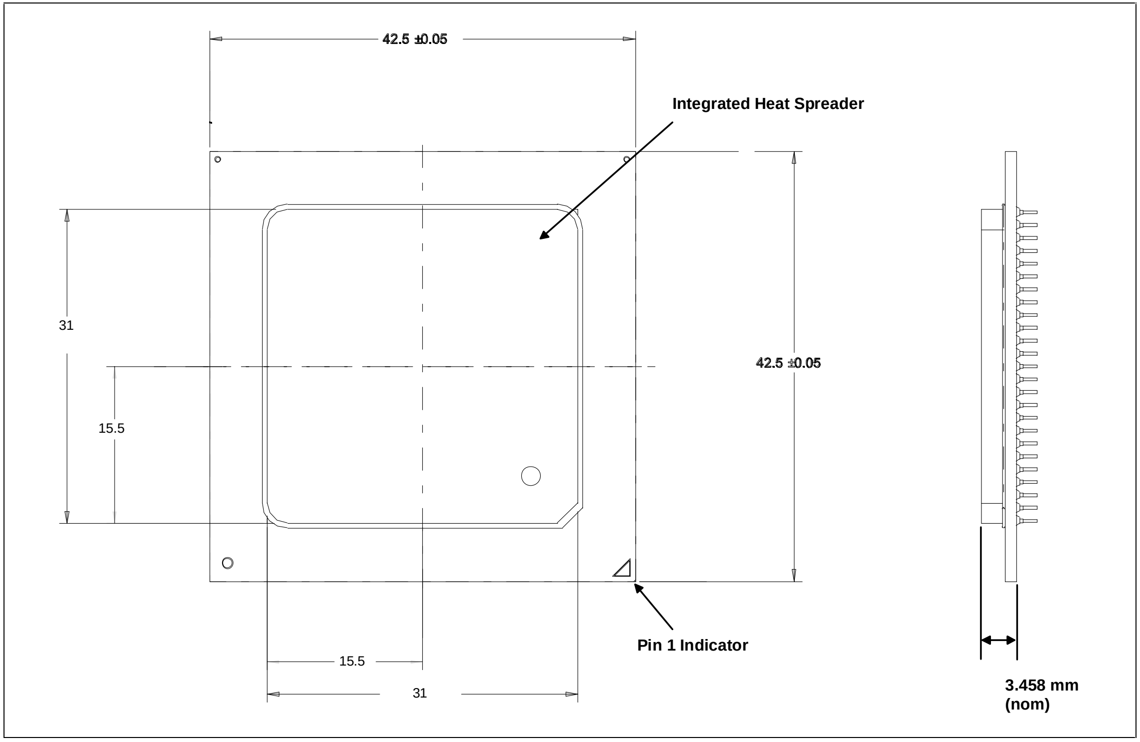


Figure 3. Intel® Xeon™ Processor with 512 KB L2 Cache Processor (31.0 mm FC-mPGA2 package)



4 Thermal Specifications

Please refer to the processor datasheet for thermal design power and maximum case temperature specifications.

In order to ease the burden on chassis cooling solutions, the Thermal Monitor feature and associated logic has been integrated into the silicon of the processor. By taking advantage of the Thermal Monitor feature, system designers may reduce the cooling system cost while maintaining the processor reliability and performance goals. Other options within the thermal management logic allow system software to monitor and control the performance and thermal characteristics of the processor. Implementation options and recommendations are described in Chapter 6.

For the purposes of this application note, the following assumptions have been made about the requirements for proper operation and reliability of the processor:

- Considering the power dissipation levels and typical system local-ambient temperatures of 35°C to 45°C [95-113°F], the processor's temperatures cannot be maintained at or below its specification without additional thermal enhancement to dissipate the heat generated by the processor.
- The thermal characterization data described in later sections illustrates that both a thermal-cooling device and system airflow is needed. The size and type (passive or active) of thermal cooling device and the amount of system airflow are related and can be traded off against each other to meet specific system design constraints. In typical systems, board layout, spacing, and component placement limit the thermal solution size. Airflow is determined by the size and number of fans along with their placement in relation to the components and the airflow channels within the system. In addition, acoustic noise constraints may limit the size, number and types of fans that can be used in a particular design.

To develop a reliable, cost-effective thermal solution, all of the above variables must be considered. Thermal characterization and simulation should be carried out on the entire system, accounting for the thermal requirements of each component.

4.1 Processor Case Temperature

The Integrated Heat Spreader (IHS) provides a common interface and attach location for all processor thermal solutions. The IHS can improve thermal solution performance by spreading the concentrated heat from the core to a larger surface area for enhanced heat transfer through the heatsink. Thermal solutions can be active or passive. Active solutions typically incorporate a fan in the heatsink and may be smaller than a passive heatsink. Considerations in heatsink design include:

- Local-ambient temperature at the heatsink
- Surface area of the heatsink
- Volume of airflow over the surface area
- Power being dissipated by the processor
- Physical volume constraints of the system
- Fan reliability (using multiple fans for redundancy)

Techniques for measuring case temperatures are provided in Chapter 5.

4.2 Processor Power

The processor power, as listed in the datasheet, is the total thermal design power that is dissipated through the IHS. This value also includes components that take into account manufacturing variations.

The processor power dissipation is documented in two ways: Maximum Power and Thermal Design Power (TDP). Maximum power can be attained while running code specifically written to draw the most current, such as the maximum power test application. While running typical applications, maximum power is not usually reached, especially for a thermally significant duration of time. As a result, the TDP is provided as the thermal design target for systems. This power target is derived from profiling multiple workstation and server applications. For any excursions beyond TDP, the Thermal Monitor feature is available to maintain processor thermal specifications. Refer to Chapter 6 and the processor datasheet for details regarding Thermal Monitor.

5 Thermal Metrology

The following sections will discuss the techniques for testing thermal solutions. It should be noted that determining if a processor is sufficiently cooled is not as simple as it may seem. Carefully read the following instructions and determine the steps required to validate your cooling solution.

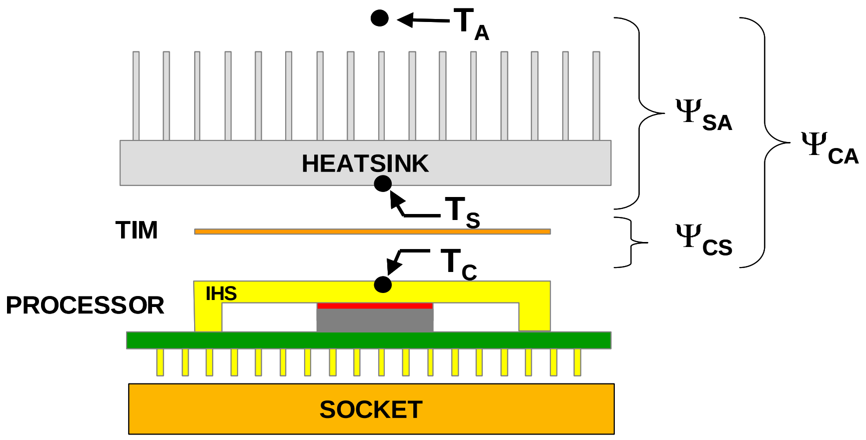
5.1 Processor Thermal Metrology

5.1.1 Thermal Resistance

The case-to-ambient thermal resistance, Ψ_{CA}, is used as a measure of the cooling solution's thermal performance. The case to local-ambient thermal resistance, Ψ_{CA}, is comprised of the case to sink (Ψ_{CS}) thermal resistance and the sink to local-ambient thermal resistance (Ψ_{SA}). Thermal resistance is measured in units of °C/W.

The case to local-ambient (Ψ_{CA}) thermal resistance is measured between the top of the IHS case and the local-ambient air. It is strongly dependent on the thermal conductivity and thickness of the TIM between the heatsink and surface of the processor IHS. The term Ψ_{SA} is a measure of the thermal resistance from the bottom of the heatsink base to the local-ambient air. Ψ_{SA} is dependent on the heatsink material, thermal conductivity, geometry, and strongly dependent on the air velocity through the fins of the heatsink (see Figure 4). Ψ_{CS} is the thermal resistance between the top of the IHS case and the bottom of the heatsink base. It is dependent on the thermal interface material thermal (TIM) conductivity, bond-line thickness, and the flatness and tilt of the heatsink and IHS mating surfaces.

Figure 4. Processor Thermal Resistance Relationships



The thermal parameters are related by the following equations:

Equation 1. Thermal Case to Ambient Thermal Resistance

$$\Psi_{CA} = (T_{CASE} - T_{LA}) / P_D$$

Equation 2. Thermal Case to Ambient Thermal Resistance

$$\Psi_{CA} = \Psi_{CS} + \Psi_{SA}$$

Where:

Ψ_{CA} = Case to local-ambient thermal resistance (°C/W)
T_{CASE} = Processor case temperature (°C)
T_{LA} = Local-ambient temperature in chassis around processor (°C)
P_D = Processor thermal design power (TDP), assuming all power is dissipated through the case (W)
Ψ_{CS} = Case to sink thermal resistance, dependent on the thermal interface material (°C/W)
Ψ_{SA} = Sink to local-ambient thermal resistance (°C/W)

5.1.2 Thermal Solution Performance

All processor thermal solutions attach to the processor at the IHS. The system thermal solution must adequately control the local-ambient air around the processor (T_{LA}). The lower the thermal resistance between the processor and the local-ambient air, the more efficient the thermal solution. The required Ψ_{CA} is dependent upon the maximum allowed processor IHS, or case temperature (T_{CASE}), the local-ambient temperature (T_{LA}), and the processor power (P_D).

Use Equations 1 and 2 to determine a target θ_{CA} and θ_{SA} using the following assumptions.

T_{CASE} = 75°C, hypothetical maximum case temperature specification
T_{LA} = Assume 45°C, a typical value for desktop systems
P_D = Assume 70 W, hypothetical thermal design power (TDP)
Ψ_{CS} = Assume 0.12°C/W

Solving for the Equation 1 from above:

$$\begin{aligned} \Psi_{CA} &= (T_{CASE} - T_{LA}) / P_D \\ &= (75 - 45) / 70 \\ &= 0.42°\text{C/W} \end{aligned}$$

Solving for Equation 2 from above:

$$\begin{aligned} \Psi_{CA} &= \Psi cs + \Psi_{SA} \\ \Psi_{SA} &= \Psi_{CA} - \Psi_{CS} \\ &= 0.42 - 0.12 \\ &= 0.30°\text{C/W} \end{aligned}$$

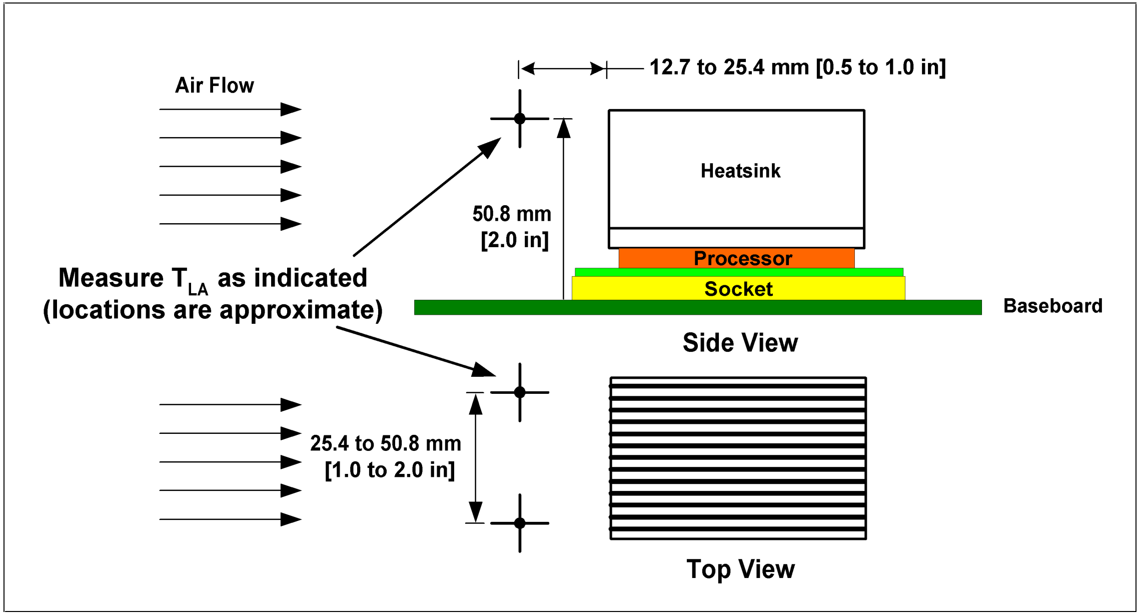
5.1.3 Local-Ambient Temperature Measurement Guidelines

Local-ambient temperature, T_{LA}, is the temperature of the ambient air surrounding the processor. In a system environment, ambient temperature is the temperature of the air upstream of the processor and in its close vicinity; in an active cooling system, it is the inlet air to the active cooling device. It is necessary to determine the local-ambient temperature in the chassis at the processor to determine the thermal performance of a given thermal solution (Ψ_{CA}).

The local-ambient temperature is best measured as an average of the localized air surrounding the processor. The following guidelines are meant to enable accurate determination of the localized air temperature around the processor during system thermal testing.

1. During system thermal testing, a minimum of two thermocouples should be placed approximately 12.7 to 25.4 mm [0.5 to 1.0 in] away from processor and heatsink as shown in Figure 5. This placement guideline is meant to minimize localized hot spots due to the processor, heatsink, or other system components.
2. The thermocouples should be placed approximately 50.8 mm [2.0 in] above the baseboard and 25.4 to 50.8 mm [1.0 to 2.0 in] apart. This placement guideline is meant to minimize localized hot spots from baseboard components.
3. T_{LA} should be the average of the thermocouple measurements during system thermal testing.

Figure 5. Locations for Measuring Local-Ambient Temperature (Not to Scale)



5.1.4 Measurements for Processor Thermal Specifications

The system integrator must make processor T_{CASE} measurements to determine whether a system or component thermal solution is adequate for maintaining a processor within thermal specifications. Guidelines have been established for proper techniques for measuring T_{CASE} temperatures. The following sections describe these guidelines for temperature measurement.

5.1.4.1 Processor Case Temperature Measurements

To ensure functionality and reliability, the processor is specified for proper operation when T_{CASE} is maintained at or below the value listed in the processor datasheet. The measurement location for T_{CASE} is the geometric center of the IHS. Figure 6 shows the location for T_{CASE} measurement.

Special care is required when measuring the T_{CASE} to ensure an accurate temperature measurement. Thermocouples are often used to measure T_{CASE}. Before any temperature measurements are made, the thermocouples must be calibrated. When measuring the temperature of a surface, which is at a different temperature from the surrounding local-ambient air, errors could be introduced in the measurements. The measurement errors can be due to a poor thermal contact between the thermocouple junction and the surface of the integrated heat spreader. Errors can also occur via heat loss by conduction through thermocouple leads, or by contact between the thermocouple cement and the heatsink base. To minimize these measurement errors, the following approaches are recommended.

5.1.4.2 Methodology for Solid Base Heatsinks (90° Angle Attach)

- Prepare a 36 gauge or finer diameter K, T, or J type thermocouple.
- Ensure that the thermocouple has been properly calibrated.
- The thermocouple should be attached at a 90° angle to the integrated heat spreader at the location specified for T_{CASE} measurement (Figure 9).
- Drill a 3.8 mm [0.150 in] maximum diameter hole through the heatsink base. This hole must be positioned on the heatsink base so that it matches with the center of the IHS when assembled. This hole will reduce the heatsink performance by approximately 0.02°C/W.
- Create a small depression, approximately 1.59 mm [1/16 inch] in diameter by 0.4 mm [1/64 inch] deep at the center of the IHS. This will facilitate the attach procedure by keeping the thermocouple centered and hosting the adhesive.
- Attach the thermocouple bead or junction to the top surface of the IHS using high thermal conductivity cements. See Figure 6, Figure 7, and Figure 8 for illustrations of the location of thermocouple attachment.
- Route the thermocouple wires through the hole in the heatsink base and attach it to the processor IHS. The use of more viscous adhesives and minimizing the use of drying accelerators will prevent problems with the adhesive spreading.
- A small fixture may be required to hold the thermocouple and apply a steady force during the curing process to ensure the thermocouple is making contact with the IHS. A digital multimeter (DMM) can be used to check continuity between the IHS and the connector as the adhesive cures.
- Make sure there is no contact between the thermocouple cement and heatsink base. Contact will affect the thermocouple reading.
- Verify the cured adhesive bead is smaller than 3.8 mm [0.150 in] in diameter and height so as to fit in the hole drilled in the heatsink base. Trim as necessary.
- Place the TIM on the heatsink base. If it is a semi-liquid type, apply it on the IHS, around the thermocouple. The clamping force will spread the TIM. If the TIM is a solid type, punch a 3.8 mm [0.150 in] diameter hole in the center of the TIM pad and cut a line from hole to edge corresponding to the slot for the thermocouple wire. This will allow the installation of the TIM to the IHS with the thermocouple already attached to the processor.

Note: Drawings are not to scale. In case of conflicts in dimensions, the processor datasheet supercedes this document. All dimensions are nominal values.

Figure 6. Intel® Xeon™ Processor T_{CASE} Measurement Location

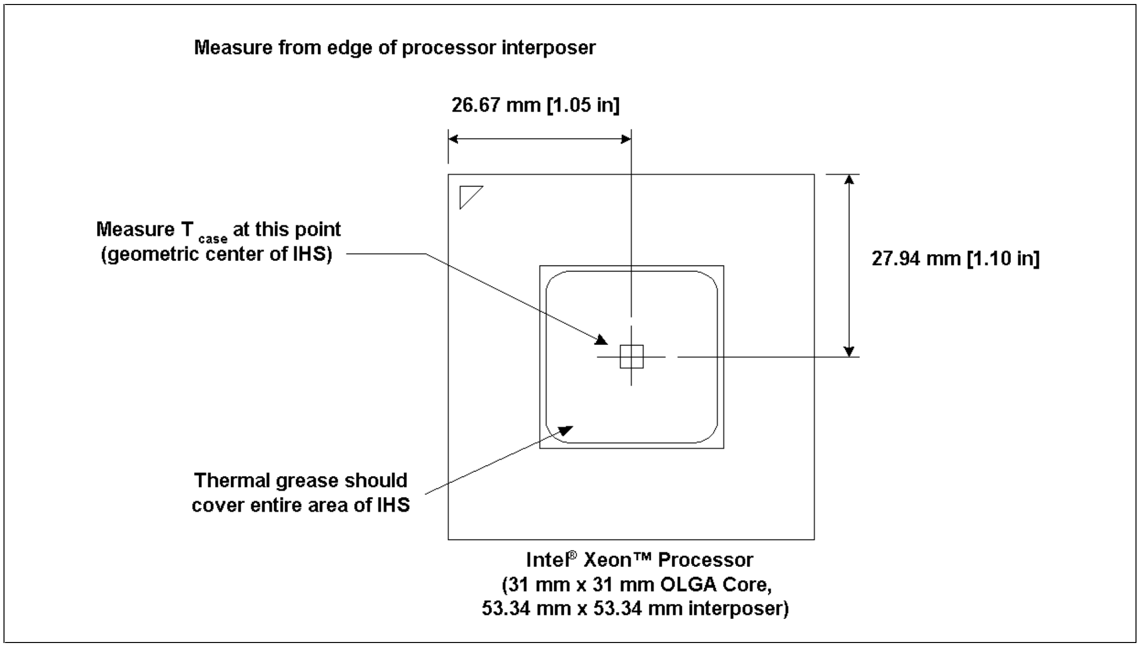


Figure 7. Intel® Xeon™ Processor with 512 KB L2 Cache (INT-mPGA) T_{CASE} Measurement Location

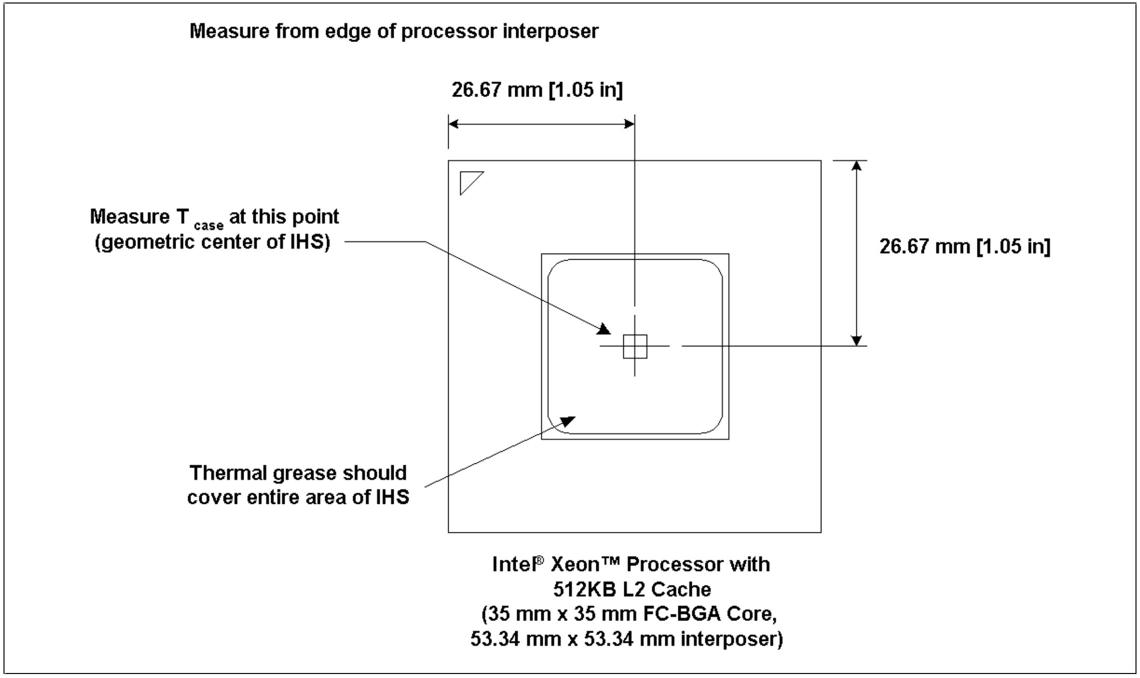


Figure 8. Intel® Xeon™ Processor with 512 KB L2 Cache (FC-mPGA2) T_{CASE} Measurement Location

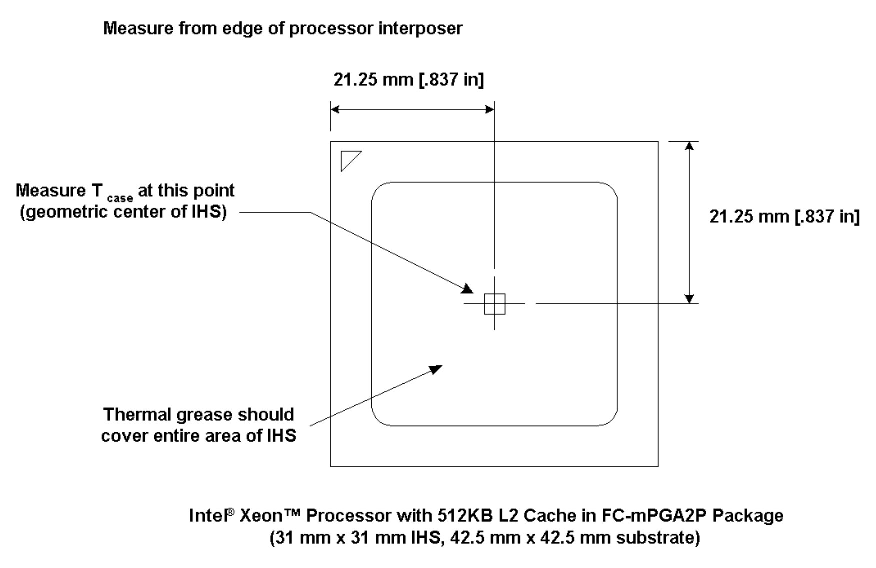
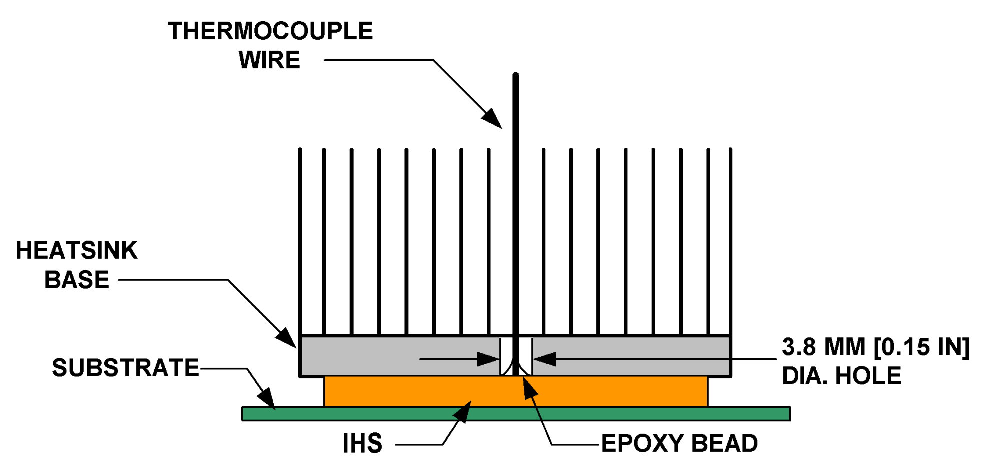


Figure 9. Technique for Measuring with 90° Angle Attachment



5.1.4.3 Methodology for 0° Angle Thermocouple Attach

1. Prepare a 36 gauge or finer diameter K, T, or J type thermocouple.
2. Ensure that the thermocouple has been properly calibrated.
3. Use a scribe to mark the geometric center on the topside of the IHS. This represents the location where the bead of the thermocouple will be placed. The center of the IHS can be obtained by measurement, or by drawing two diagonal lines across the length of the IHS. The cross-point will be the geometric center of the IHS. Figure 6 and Figure 7 show the thermocouple location relative to the IHS and processor interposer substrate.

4. After the marks are scribed, clean the desired thermocouple attach location with a mild solvent and a lint-free wipe or cloth. Alcohol or acetone should suffice. Remember that the cleaner the part is, the stronger the bond will be after curing.

5. Straighten the thermocouple wire by hand so that the first 100 to 150 mm [4 to 6 inches] are reasonably straight. Use fine point tweezers to make sure that the bead and the two wires coming out are straight and untwisted. Make sure that the second layer of thermocouple insulation, sometimes clear, is not covering the bead.

6. Create a slight downward bend in the wires about 1.6 mm [1/16 inch] from the bead. Once the thermocouple is in place, this will guarantee that the thermocouple bead is making contact with the surface.

7. Place the thermocouple bead on the geometric center of the IHS (previously scribed). Apply Kapton* tape across the wire about 6 mm [0.25 inch] back from the bead to hold the thermocouple in place. Apply pressure to the tape to ensure a good bond. Apply additional tape pieces along the length of the wire to ensure a good temporary bond to the part. Check the electrical continuity between the thermocouple and the IHS using a multi-meter. If there is no electrical continuity between the thermocouple and the IHS, repeat steps 5 through 7.

8. With the thermocouple in place, the epoxy can now be mixed and applied. Follow the manufacturer's directions for mixing the epoxy.

9. Use a clean, finely pointed applicator to apply the epoxy to the bead. Dab the epoxy bond on the bead and the exposed wires. Use only the appropriate amount of glue to cement the thermocouple down. The entire bead should be submerged and it is best to have insulated wires protruding from the glue.

10. Additional beads of epoxy can be added, off of the IHS surface, along the length of wire to provide strain relief for the thermocouple wire. Only one epoxy bead should be on the IHS surface.

11. Cure the epoxy according to the manufacturer's instructions. The cure temperature should remain below 65°C [150°F] if possible. Make sure the vibration in the oven is minimal to prevent the thermocouple bead from moving. Another alternative is to cure the epoxy at room temperature for a duration recommended by the manufacturer.

12. Once the epoxy has cured, remove all tape and check for any residual epoxy outside the thermocouple attach area on the IHS. Run the tip of your finger around the IHS surface to find any small glue dots. Remove any residual glue to prevent any impact on bond line or heatsink attach.

13. Verify the cured adhesive bead at the IHS center is smaller than 3.8 mm [0.15 inch] in diameter and 0.63mm [0.025 inch] in height so as to fit in the groove machined in the heatsink base. Trim as necessary.

14. Check the electrical continuity between the thermocouple and the IHS again. If there is no electrical continuity between the thermocouple and the IHS, repeat steps 4-12.

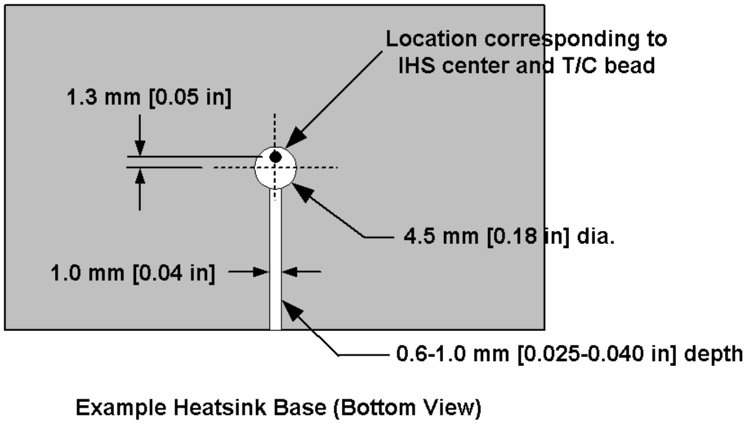
15. Place the TIM on the heatsink base. If it is a paste, apply it on the IHS around the thermocouple. The clamping force will spread the TIM. If the TIM is a solid pad, punch a 0.15 inch [3.8 mm] diameter hole in the center of the TIM pad and cut a line from a side to the hole. This will allow the installation of the TIM to the IHS with the thermocouple already attached to the IHS.

16. In order to measure the case temperature as accurately as possibly, the heatsink must be grooved to allow room for the thermocouple wires and attach point. Depending on the heatsink, the dimensions of the groove location may vary. The system integrator should perform the appropriate

analysis to define the placement dimensioning for a specific thermal design. It is imperative that the heatsink groove is aligned with the thermocouple wires and bead. Any discrepancy will cause the heatsink to sit improperly on the IHS surface and provide erroneous data. A 1.0 mm [0.040 in] wide groove with a depth of 0.6-1.0 mm [0.025-0.040 in] should be milled into the heatsink base. A circular area should be milled out to accommodate the epoxy surrounding the thermocouple bead (~4.5 mm [0.18 in] diameter, 0.6-1.0 mm [0.025-0.040 in] deep). The center of the circular area should be located 1.3 mm [0.05 in] off center from the location corresponding to the thermocouple bead. The offset ensures that the circular area accommodates the entire epoxy bead that covers both the thermocouple bead and the exposed thermocouple wires. See Figure 10 for an example of a heatsink base grooved for thermocouple installation.

Note: Figure is not to scale and is for reference only.

Figure 10. Example Groove in Heatsink Base for Thermocouple Installation



5.1.5 Thermal Testing Software

The Intel Xeon processor and Intel Xeon processor with 512 KB L2 cache thermal testing software is a Microsoft* Windows* 32-bit application that runs within a command prompt window. This software is intended for thermal evaluation purposes only and is not a general-purpose application. The software does not generate the maximum processor power as defined in the processor datasheet. This software does provide system designers with an application nearing worst-case power consumption for the analysis and validation of system cooling solutions. Differences between the observed thermal power measurements and the maximum power dissipation indicated in the datasheet can be attributed to process and test variation, system configuration differences and potential thermal testing software optimizations. Details regarding the execution of the thermal testing software are provided in the “readme” file included in the software package. Contact your Intel Field Sales representative for the latest copy of the thermal testing software.

6 Thermal Management Logic and New Thermal Monitor Feature

6.1 Processor Power Dissipation

An increase in processor operating frequency not only increases system performance, but also increases the processor power dissipation. The relationship between frequency and power is generalized in the following equation: $P = CV^2F$ (where P = power, C = capacitance, V = voltage, F = frequency). From this equation it is evident that power increases linearly with frequency and with the square of voltage. In the absence of power saving technologies, ever increasing frequencies will result in processors with power dissipations in the hundreds of watts. Fortunately, there are numerous ways to reduce the power consumption of a processor. Decreasing the voltage and transistor size are two examples, a third is clock modulation, which is used extensively in laptop designs.

Clock modulation is defined as periodically removing the clock signal from the processor core, which effectively reduces its power consumption to a few watts. A zero watt power dissipation level is not achievable due to transistor leakage current and the need to keep a few areas of the processor active (cache coherency circuitry, phase lock loops, interrupt recognition, etc.). Therefore, by cycling the clocks on and off at a 50% duty cycle, for example, the average power dissipation can drop by up to 50%. Note that the processor performance will also drop by about 50% during this period, since program execution halts while the clocks are removed. Varying the duty cycle will have a corresponding influence on power dissipation and processor performance. The duty cycle is specific to the processor (typically 30-50%).

Laptop systems use clock modulation to control system and processor temperatures. By using various external measurement devices, laptops monitor the processor case temperature and turn on fans or initiate clock modulation to reduce processor power dissipation and ensure that all elements of the system operate within their temperature specification. Unfortunately, using external thermocouples connected to the processor package to monitor and control a thermal management solution has some inherent disadvantages. Thermal resistance through the processor package creates a temperature delta between the processor case and silicon. This delta may be large, with the silicon temperature always being higher than the case temperature (under normal operating circumstances). Since thermocouples measure case temperature, not silicon temperature, significant added margin may be necessary to ensure the processor silicon does not exceed its maximum specification. (i.e., clock modulation may have to be turned on when the case temperature is well below the maximum specification to ensure that the processor does not overheat). This added margin might have a substantial, and unacceptable, impact on system performance.

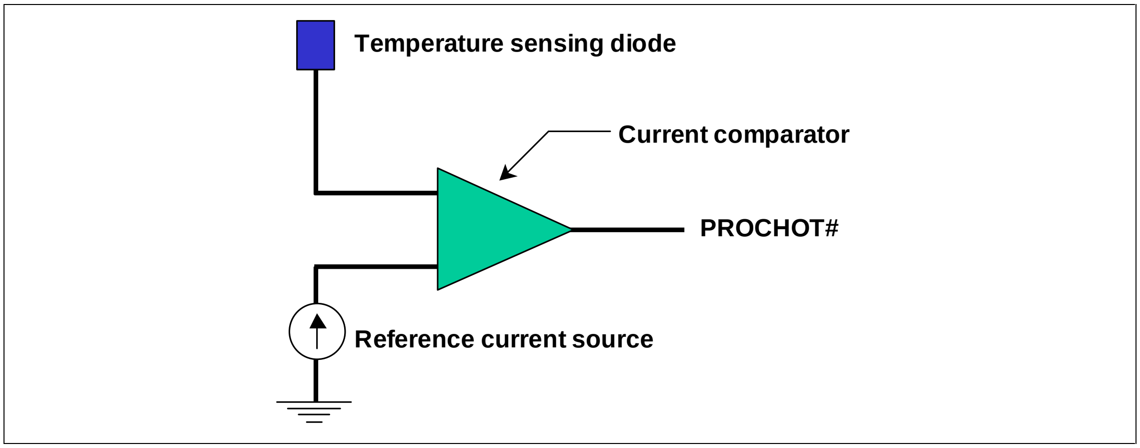
The thermal ramp rate, or change in die temperature over a specified time period ($\Delta T/\Delta t$), may be extremely high in high power processors. Ramp rates in excess of 50°C/s may occur in the course of normal operation. With this type of thermal characteristic, it would not be possible to control fans or other cooling devices based on processor core temperature. By the time the fans have spun up to speed, the processor may be well beyond a safe operating temperature. Just as large added margins would be necessary to account for package thermal gradients, large margins would also be necessary if temperature-controlled fans were implemented.

An on-die thermal management feature called Thermal Monitor is available on the Intel Xeon processor and the Intel Xeon processor with 512 KB L2 cache. It provides a thermal management approach to support the continued increases in processor frequency and performance. It resolves the issues discussed above so that external thermocouples are no longer needed. By using a highly accurate on-die temperature sensing circuit, and a fast acting temperature control circuit, the processor can rapidly invoke thermal management mechanisms as necessary to control the die temperature. As a result, added thermal design margins can be significantly reduced and the resulting system performance impact can be minimized if not eliminated.

6.2 Thermal Monitor Implementation

On the processor the thermal monitor is integrated into the processor silicon. The thermal monitor includes a highly accurate on-die temperature sensing circuit, a signal that indicates the processor has exceeded temperature limits (PROCHOT#), a thermal control circuit (TCC) that can reduce processor temperature by controlling the duty cycle of the processor clocks, and registers to determine the processor thermal status. The processor temperature is determined through an analog thermal sensor circuit comprised of: a diode, a factory calibrated reference current source, and a current comparator (see Figure 11). A voltage applied across the diode will induce a current flow that varies with temperature. By comparing this current with the reference current, the processor temperature can be determined. The reference current source corresponds to the diode current when at the maximum permissible processor operating temperature. Each processor is individually calibrated during manufacturing to eliminate any potential manufacturing variations. Once configured, the processor temperature at which the PROCHOT# signal is asserted (trip point) is not reconfigurable.

Figure 11. Thermal Sense Circuit

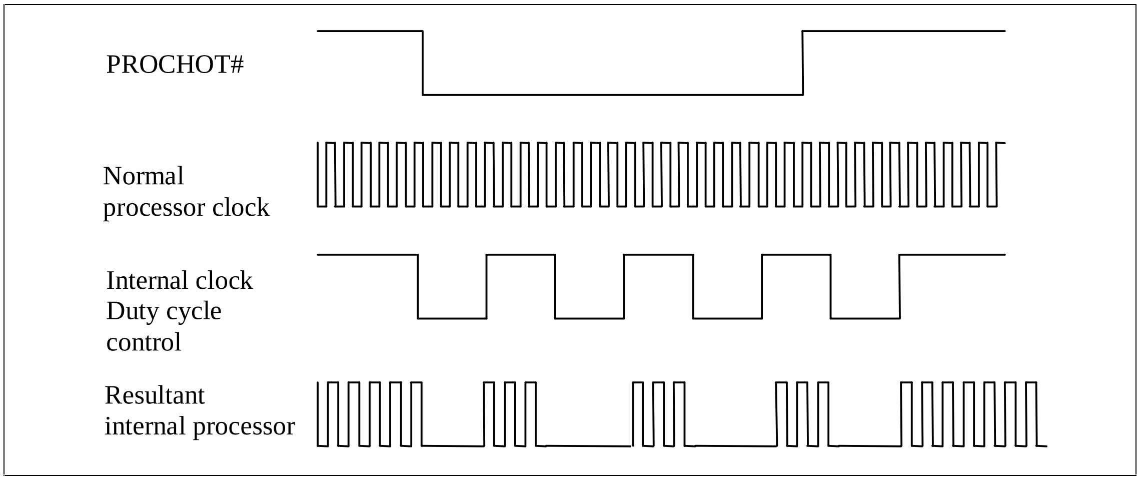


The PROCHOT# signal is used both internal to the processor as well as external to the system. External indication of the processor temperature status is provided through the bus signal PROCHOT#. When the processor temperature reaches the trip point, PROCHOT# is asserted. When the processor temperature is below the trip point, PROCHOT# is deasserted. Assertion of the PROCHOT# signal is independent of any register settings within the processor. It is asserted any time the processor die temperature reaches the trip point. The point where the thermal control circuit activates is set to the same temperature at which the processor is tested.

The thermal monitor’s thermal control circuit, when active, lowers the processor temperature by reducing the duty cycle of the internal processor clocks. The thermal control circuit portion of the thermal monitor must be enabled by the system BIOS for the processor to be operating within specifications. When active, the thermal control circuit turns the processor clocks off and then back on with a predetermined duty cycle.

The actual duty cycle will vary from one product to another. Refer to Figure 12 for an illustration. Cycle times are processor speed dependent and will decrease as processor core frequencies increase.

Figure 12. Concept for Clocks Under Thermal Monitor Control



Performance counter registers, status bits in model specific registers (MSRs), and the PROCHOT# output pin are available to monitor and control the thermal monitor behavior. Details regarding the use of these registers are described in the *IA-32 Intel® Architecture Software Developer's Manual,* Volume 3: System Programming Guide.

In addition to the thermal monitor, the processor clocks can also be modulated via an ACPI register that is implemented as an MSR on the processor core. This is referred to as "on demand mode" clock modulation. See Section 0 for additional details.

6.3 Operation and Configuration

To maintain compatibility with previous generations of processors, which have no integrated thermal management logic, the thermal control circuit portion of the thermal monitor is disabled by default. During the boot process, the BIOS must enable the thermal control circuit; or a software driver may do this after the operating system has booted. Refer to the *IA-32 Intel® Architecture Software Developer's Manual,* Volume 3: System Programming Guide for specific programming details.

The thermal control circuit can be configured and monitored in a number of ways. OEMs are expected to enable the thermal control circuit while using various registers and outputs to monitor the processor thermal status. The thermal control circuit is enabled by the BIOS setting a bit in a MSR (model specific register). Enabling the thermal control circuit allows the processor to maintain a safe operating temperature without the need for special software drivers or interrupt handling routines. When the thermal control circuit has been enabled, processor power consumption will be reduced within a few hundred clock cycles after the thermal sensor detects a high temperature (i.e. within a few hundred clock cycles of PROCHOT# assertion). The thermal control circuit and PROCHOT# go inactive once the temperature has been brought back down below the thermal trip point, although a small hysteresis (~1°C) has been included to prevent multiple PROCHOT# transitions around the trip point.

External hardware can monitor PROCHOT# and generate an interrupt whenever there is a transition from active-to-inactive or inactive-to-active. PROCHOT# can also be configured to generate an internal interrupt which would initiate an OEM supplied interrupt service routine. Regardless of the configuration selected, PROCHOT# will always indicate the thermal status of the processor.

For testing purposes, the thermal control circuit may also be activated by setting bits in the ACPI MSRs. The MSRs may be set based on a particular system event (such as an interrupt generated after a system event), or may be set at any time through the operating system or custom driver control thus forcing the thermal control circuit on. This is referred to as "on-demand" mode. Activating the thermal control circuit may be useful for cooling solution investigations or for performance implication studies. When using the MSRs to activate the thermal monitor feature, the duty cycle is configurable in steps of 12.5% from 12.5 to 87.5%.

For any duty cycle, the maximum time the clocks will be disabled is ~3 µs. This time period is frequency dependent, and decreases as frequency increases. To achieve different duty cycles, the length of time that the clocks are disabled remains constant, and the time period that the clocks are enabled is adjusted to achieve the desired ratio. For example, if the clock disable period is 3µs, and a duty cycle of ¼ (25%) is selected, the clock on time would be reduced to approximately 1 µs [on time (1 µs)÷ total cycle time (3 + 1) µs = ¼ duty cycle]. Similarly, for a duty cycle of 7/8 (87.5%), the clock on time would be extended to 21 µs [21 ÷ (21 + 3) = 7/8 duty cycle].

In a high temperature situation, if the thermal control circuit and ACPI MSRs (automatic and on-demand modes) are used simultaneously, the fixed duty cycle determined by automatic mode would take precedence.

6.4 System Considerations

The thermal monitor feature may be used in a variety of ways, depending upon the system design requirements and capabilities. Intel requires the thermal monitor and the thermal control circuit to be enabled for all Intel Xeon processor-based designs. At a minimum, the thermal control circuit supplies an added level of protection against processor over-temperature failure. Current thermal design power (TDP) targets are significantly higher than previous generation Intel® Pentium® III Xeon™ processors (refer to the appropriate processor datasheet for specific TDP targets).

To minimize the cost of a processor thermal solution, system designers are encouraged to take advantage of the thermal monitor feature. The thermal monitor feature allows processor thermal solutions to design to the thermal design power (TDP) target, as opposed to maximum processor power consumption. Designing to the lower TDP target results in a lower thermal solution cost, while still maintaining a level of processor performance that is virtually indistinguishable from systems designed to manage maximum power dissipation levels.

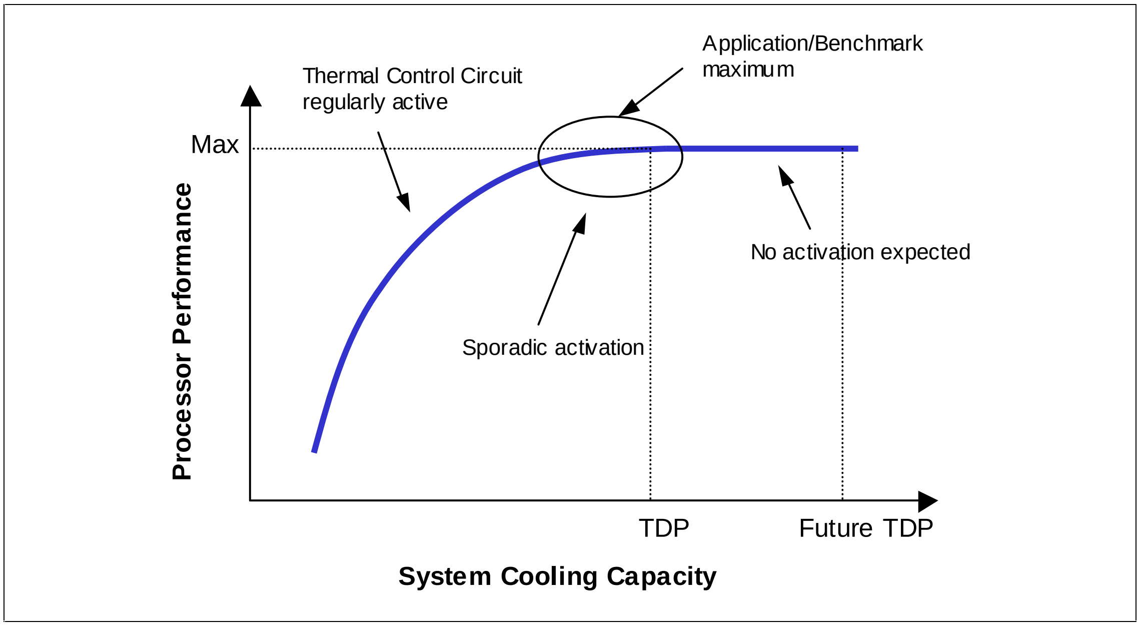
Each application program, which is comprised of thousands of processor instructions, will have its own unique power profile, and the profile will have some variability due to loop decisions, I/O activity and interrupts. In general, compute intensive applications with a high cache hit rate will dissipate more processor power than applications that are I/O intensive or have low cache hit rates.

The processor thermal design power is based on measurements of processor power consumption while running various high power applications. This data was used to determine those applications that are interesting from a power perspective. These applications were then evaluated in a controlled thermal environment to determine their sensitivity to activation of the thermal control circuit. This data was used to derive the thermal design power targets published in the processor datasheet.

A system designed to meet the thermal design power (TDP) and T_{case} specifications in the processor datasheet greatly reduces the probability of real applications causing the thermal control circuit to activate under normal operating conditions. Systems that do not meet these specifications could be subject to more frequent activation of the thermal control circuit, depending upon ambient air temperature and application power profile. If a designer significantly derates the thermal design power, there is a risk that the thermal monitor feature will not be capable of maintaining a safe operating temperature and the processor could shutdown and signal THERMTRIP#. For details regarding the THERMTRIP# signal, refer to Section 6.5.2 or to the processor datasheet.

Figure 13 plots processor performance with the thermal monitor feature enabled vs. system cooling capability. System designers must evaluate the tradeoffs between cooling costs and risk of processor performance loss to determine the optimum configuration for the end user.

Figure 13. Processor Performance vs. System Cooling Capability



6.4.1 Operating System and Application Software Considerations

The thermal monitor feature and its thermal control circuit work seamlessly with any ACPI compliant operating system, provided system BIOS support exists. The thermal monitor feature is transparent to application software since the processor bus snooping, ACPI timer and interrupts are active at all times.

6.4.1.1 Operating System Support

Activation of the thermal control circuit during a non-ACPI aware operating system boot process may result in incorrect calibration of software timing loops. The BIOS must disable the thermal control circuit during boot and then the operating system or BIOS must enable the thermal control circuit after the operating system boot process completes. Refer to the *IA-32 Intel® Architecture Software Developer's Manual*, Volume 3: System Programming Guide for specific programming details.

Intel is working with the major operating system vendors to ensure support for non-execution based operating system calibration loops and ACPI support for the thermal monitor feature. Per Microsoft*, Microsoft Windows 98ES and Microsoft Windows 2000 use non-execution based calibration loops and therefore have no issues with the thermal monitor feature. When installing Microsoft Windows NT* 4.0, the user must ensure the PIC-based HAL is used. It is expected that other OS solutions (Linux*, UNIX*, etc) will provide updates to ensure compatibility.

6.5 Legacy Thermal Management Capabilities

In addition to the thermal monitor feature, the Intel Xeon processor and the Intel Xeon processor with 512 KB L2 cache supports the same thermal management features available with the Pentium III Xeon processors. These features include the Thermal Reference Byte located in the processor information ROM (PIROM), SMBus access to the on-die thermal sensor, and the THERMTRIP# signal for indicating catastrophic thermal failure.

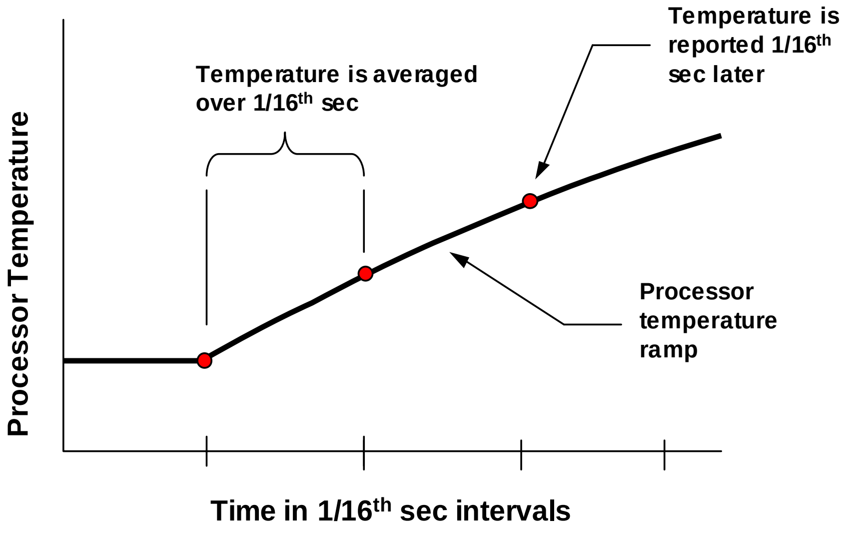
6.5.1 Thermal Sensor

The processor incorporates the SMBus thermal sensor and Thermal Reference Byte features previously enabled for the Intel Pentium III Xeon processor family. Using the SMBus interface, the processor temperature, as measured by the thermal diode, may be read. By averaging this data over long time periods (hours/days vs. min/sec), it may be possible to derive a trend of the processor temperature. Analysis of this information could be useful in detecting changes in the system environment that may require attention.

The processor Thermal Reference Byte is best used for steady state analysis of the processor cooling solution. Attempting to predict the thermal management logic's behavior based on Thermal Reference Byte comparisons is not possible due to the previously described thermal ramp rates. The Thermal Reference Byte is not individually calibrated on the processor, but is generally characterized.

The processor thermal diode should not be relied upon to turn on fans, warn of processor cooling system failure or predict the onset of the thermal control circuit. As mentioned earlier, the processor's high thermal ramp rates make this unfeasible. An illustration of this is as follows: Many thermal sensors report temperatures at a maximum of 8 times per second. Within the 1/8th (0.125 sec) second time period, the temperature is averaged over 1/16th of a second. In a worst-case scenario where the silicon temperature ramps at 50°C/sec, or approximately 6°C/0.125 sec, the processor will be 4.5°C above the temperature reported by the thermal sensor. (Change in diode temperature averaged over 1/16th seconds = 1.5°C, temperature reported 1/16th second later at 1/8th second when the actual processor temperature would be 6°C higher.) The ramp rate error is shown graphically in Figure 14.

Figure 14. Thermal Sensor Time Delay



6.5.2 THERMTRIP#

In the event of a catastrophic cooling failure, the processor will automatically shut down when the silicon temperature has reached approximately 135°C. At this point the system bus signal THERMTRIP# will go active and stay active until the processor has cooled down and RESET# has been initiated. THERMTRIP# activation is independent of processor activity and does not generate any bus cycles.

Power must be removed from a processor within 0.5 seconds of THERMTRIP# activation to protect the processor from thermal runaway and permanent damage. Because workstation and server designs that employ multiple processors utilize a shared power plane, power supply sources to all processors must be disabled when any installed processor signals THERMTRIP#. Refer to the processor datasheet for timing requirements when designing a circuit to remove power from the processor after THERMTRIP# assertion.

6.5.3 Thermal Measurement Correlation

There are two independent thermal diodes integrated into the processor silicon; one for use with the SMBus thermal sensor and one for the thermal monitor feature, which is also used for THERMTRIP#. The thermal monitor temperature sensor and the SMBus thermal sensor are independent and isolated devices with no direct correlation to one another. Circuit constraints and their performance requirements prevent the thermal monitor sensor and the SMBus thermal sensor from being located at the same place on the silicon. As a result, it is not possible to predict the activation of the thermal control circuit by monitoring the SMBus thermal sensor.

6.6 Cooling System Failure Warning

If desired, the system can be designed to cool the maximum processor power. In this situation, it may be useful to use the PROCHOT# signal as an indication of cooling system failure. Messages could be sent to the system administrator to warn of the cooling failure, while the thermal control circuit would allow the system to continue functioning or allow a graceful system shutdown. If no thermal management action is taken, the silicon temperature may exceed ~135°C causing THERMTRIP# to go active and shut down the processor. Regardless of the system design requirements or cooling solution ability, the thermal monitor feature must still be enabled for proper processor operation.

7 Thermal Solution Functional Specifications

This section details the thermal, mechanical, and quality guidelines and requirements for designing thermal solutions for the Intel Xeon processor and the Intel Xeon processor with 512 KB L2 cache in the 1U form factor and 2U and above form factors. Environmental reliability requirements and heatsink critical-to-function dimensions are discussed. Also, the Intel reference thermal solutions are presented. With this information, a "third party" could design a thermal solution for the Intel Xeon processor and the Intel Xeon processor with 512 KB L2 cache in all form factors.

7.1 Thermal Solution Components

The processor thermal solution(s) shall consist of the following components:

- Heatsink
- Thermal interface material (TIM)
- Heatsink clips
- Retention mechanisms (RM)
- Bypass limiting foam (for the 1U form factor only)

Figure 15 shows the fully assembled and exploded view of the thermal solution components (except for the TIM) for 2U and above form factors. The EMI grounding frame shown in Figure 15 is an optional component.

Figure 16 shows the fully assembled and exploded view of the thermal solution components (except for the TIM) for the 1U form factor.

7.2 Design Requirements

7.2.1 Thermal Design Requirements

Thermal solution components should be designed to be in compliance with thermal specifications documented in the processor datasheet and the design constraints identified in this document. Table 1 presents the system design constraints that can be found in typical server and workstation chassis. Workstation chassis may need to implement ducting to achieve this level of airflow.

Table 1. System Design Constraints

Maximum Local Ambient Temperature	Minimum Airflow	Maximum Heatsink Pressure Drop
45°C	22 CFM (2U) 10 CFM (1U)	0.15 inches H_20

Figure 15. Exploded View of Thermal Solution Components for 2U and above (2U+)

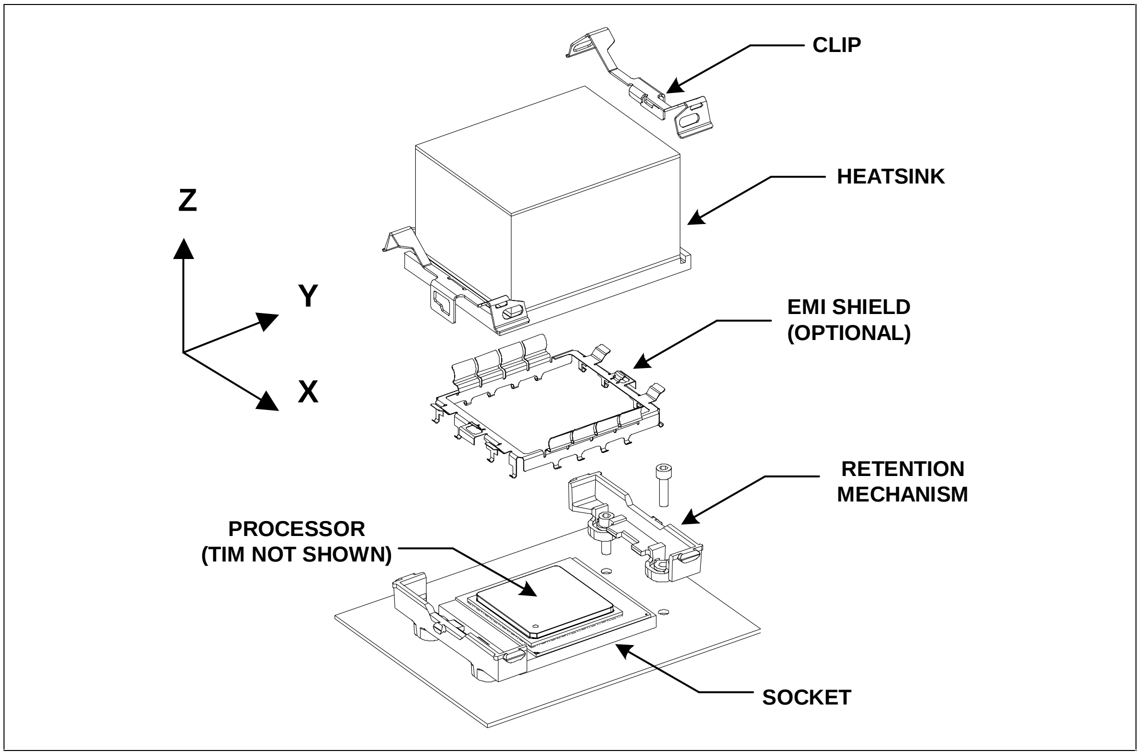
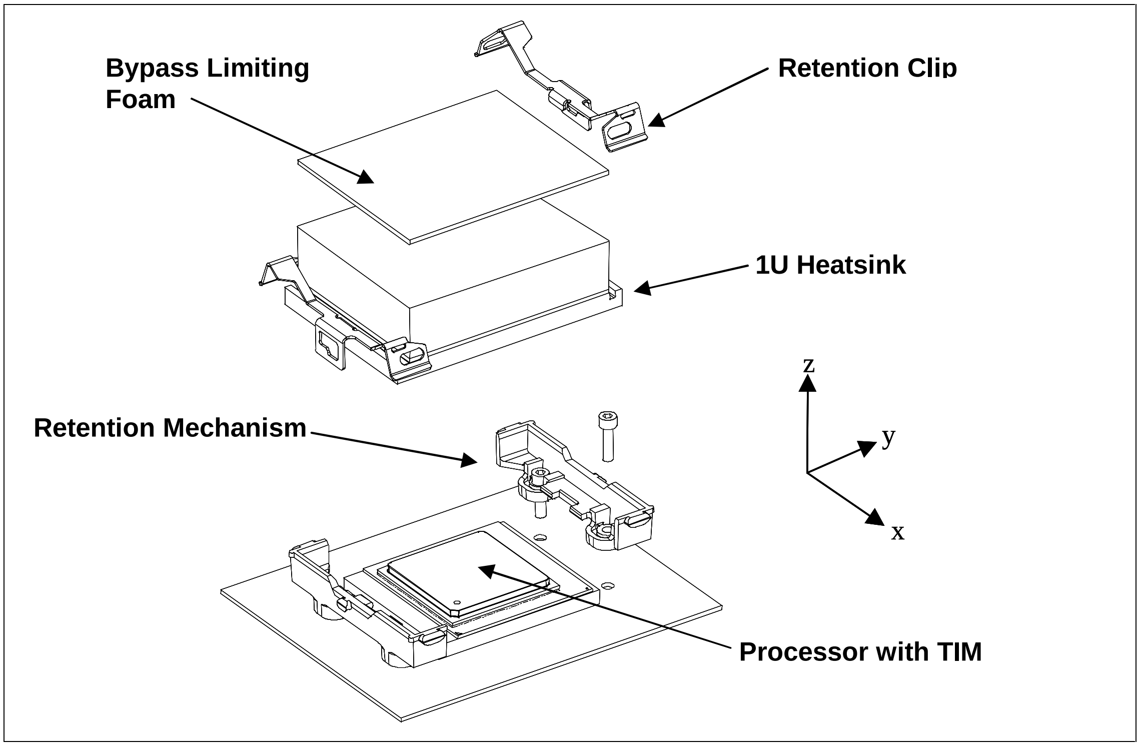


Figure 16. Exploded View of Thermal Solution Components for 1U



For a given chassis, the Ψ_{CA} requirement is based on the chassis local ambient characteristics and the processor thermal specifications (T_{case}). The processor thermal solution is required to meet the overall Ψ_{CA} requirement of the system that it serves. While Ψ_{CA} is constrained to meet system and processor requirements, Ψ_{CS} and Ψ_{SA} are independently constrained. Refer to Section 5.1.1 for definition of thermal resistance relationships, and to Figure 4 for a graphical representation of these relationships.

The reference heatsink solutions are evaluated at sea level. However, many system designs must function reliably at high altitude, typically 1,500m [5,000 ft] or more, and must account for altitude effects on overall thermal performance. Air density changes with altitude may degrade thermal performance for air-cooled thermal solutions. The system designer should account for altitude effects on the overall system thermal design to ensure that temperature specifications for the processor are met at the targeted altitude.

7.2.2 Mechanical Design Requirements

7.2.2.1 2U Heatsink Critical-to-Function Dimensions

Table 2 lists the critical-to-function (CTF) dimensions for any 2U+ heatsink compatible with the enabled retention components. The Intel reference heatsink adheres to these CTF dimensions. Figure 26 in Appendix B provide the drawings detailing the critical-to-function (CTF) dimensions. Letter references in Table 2 highlight the CTF dimensions in Figure 26.

System integrators that choose to utilize alternative heatsink solutions, such as an actively cooled fan heatsink, should refer to the required mechanical envelope provided by the alternative heatsink vendor. The mechanical envelope should include any required clearances above or around the heatsink assembly for adequate airflow into the heatsink fan. Any alternative heatsinks intended for use with the enabled clips and retention mechanism should possess the CTF heatsink base dimensions (Figure 25) and stay within the heatsink fin volumetric envelope in the X-Y direction (parallel to the heatsink base, Figure 26). Excursions beyond the envelope in the +Z direction may be acceptable depending on specific chassis clearances and alternative heatsink dimensional requirements.

7.2.2.2 1U Heatsink Critical-to-Function Dimensions

Table 3 lists the critical-to-function (CTF) dimensions for any 1U heatsink compatible with the enabled retention components. The Intel reference heatsink adheres to these CTF dimensions. Figure 27 in Appendix B provides the drawings detailing the critical-to-function (CTF) dimensions. Letter references in Table 3 highlight the CTF dimensions in Figure 27.

7.2.2.3 SSI Dimensional Requirements

The heatsink mechanical envelope must fit within the corresponding system chassis. An effort is underway by the System Server Infrastructure (SSI) initiative to standardize chassis mechanical and electrical specifications for the server and workstation industry. It is advantageous for heatsink designs to be compatible with SSI mechanical constraints in order to reduce redesign costs and ensure compatibility with future system designs. Adopted chassis definitions include the high-end, midrange, and entry electronics bay. A thin electronics bay specification adoption is in process. More information can be found at http://www.ssiforum.org.

Table 4summarizes some of the maximum component height requirements for SSI chassis (all dimensions are superceded by the most current SSI specification).

Table 2. Critical-to-Function Dimensions

Dimension	Letter	Minimum	Maximum
Location of Clip Attach Groove Far Edge from Heat Sink Edge	A	0.180 in	0.200 in
Width of Clip Attach Groove	B	0.080 in	0.100 in
Base Thickness in Zone A	C	0.245 in	0.255 in
Base Length	D	3.488 in	3.512 in
Base Width	E	2.488 in	2.512 in
Base Flatness in Zone B	F	---	0.002 in/in
Width of clip attach area (Zone A)	G	0.200 in	---
Height of Thermal Solution	---	---	2.000 in

Table 3. Critical-to-Function Dimensions

Dimension	Letter	Minimum	Maximum
Location of Clip Attach Groove Far Edge from Heat Sink Edge	A	0.180 in	0.200 in
Width of Clip Attach Groove	B	0.080 in	0.100 in
Base Thickness in Zone A	C	0.245 in	0.255 in
Base Length	D	3.488 in	3.512 in
Base Width	E	2.488 in	2.512 in
Base Flatness in Zone B	F	---	0.002 in/in
Width of clip attach area (Zone A)	G	0.200 in	---
Height of Thermal Solution	---	---	0.885 in

Table 4. SSI Chassis Height Requirements

Chassis Definition	Maximum Component Height
High-End Electronics Bay (Quad IA-32 processors)	71.12 mm [2.8 in]
Mid-Range Electronics Bay	152.4 mm [6.0 in]
Entry-Level Electronics Bay	152.4 mm [6.0 in] (114.6 mm [4.51 in] for 3U option)

NOTES: These height requirements do not include baseboard thickness or clearance above chassis.

7.2.2.4 Maximum Heatsink Mass

Heatsinks that attach to the processor via the reference retention mechanism should not exceed 450 grams.

7.2.2.5 Heatsink Center of Gravity

The center of gravity of the processor thermal solution should be located over the center of gravity of the package. For a 2U+ heatsink at the recommended maximum mass of 450 grams, the height of the center of gravity should remain below 12.7 mm [0.5 in] above the bottom of the heatsink base. For heatsinks with mass less than 450 grams, moderate excursions above the recommended limit are acceptable.

The height of the center of gravity of the 1U heatsink should remain below 0.3 in maximum from the bottom of the heatsink base.

7.2.2.6 Heatsink Base Requirements

The flatness of the base shall be maintained at 0.002 in/in maximum at the localized area (Zone B) as shown in Figure 25 and Figure 25 (see Appendix B). The base plate contains no keying features and thus can be rotated 180 degrees. A heatsink supported by the RM must incorporate two clip attach areas with a minimum width of 0.200 in (Zone A). The heatsink attach clip requirements are presented in Section 7.2.2.8.

7.2.2.7 Thermal Interface Material

A thermal interface material (TIM) must be applied between the package and the heatsink to ensure thermal conduction. The Intel Xeon processor reference thermal solution design uses Shin-Etsu* G749 thermal grease. An improved thermal grease, Shin-Etsu G751, is recommended for use with reference thermal solutions for the Intel Xeon processor with 512 KB L2 cache. The use of thermal grease in conjunction with high performance heatsink technologies (e.g. copper base crimped fin) has been demonstrated to meet Intel thermal performance requirements.

Table 6 provides the recommended grease dispense weights to ensure full coverage of the processor IHS. For alternate TIMs, full coverage on Zone B of the heatsink base as shown in Figure 25 is recommended to ensure that the entire processor IHS is covered. It will be important to compensate for heatsink to package attach alignment when selecting the proper size of a pre-applied or solid pad-type TIM. If a pre-applied thermal interface material is specified, it may have a protective application tape that must be removed prior to heatsink attach to the processor.

The use of thermally conductive greases as the thermal interface material requires special handling and dispense guidelines. The following guidelines apply only to Shin-Etsu G749 and G751 thermal grease. The use of a semi-automatic dispensing system is recommended for high volume assembly to ensure an accurate amount of grease is dispensed on top of the IHS prior to assembly of the heatsink. A typical dispense system consists of an air pressure and timing controller, a hand held output dispenser, and an actuation foot switch. Thermal grease in cartridge form is required for dispense system compatibility. A precision scale with an accuracy of ±5mg is recommended to measure the correct dispense weight and set the corresponding air pressure and duration. The IHS surface should be free of foreign materials prior to grease dispense

Additional recommendations include recalibrating the dispense controller settings after any 2 hour pause in grease dispense. The grease should be dispensed just prior to heatsink assembly to prevent any degradation in material performance. Once grease dispense is started, all the grease should be used up or disposed of in appropriate waste containers. (Contact your Environmental, Health, and Safety representative to determine disposal requirements.) Finally, the thermal grease should be verified to be within its recommended shelf life before use.

7.2.2.8 Heatsink Clip Requirements

Heatsink attach clips apply force to the heatsink base to maintain desired pressure on the thermal interface material between the package and the heatsink, and holds the heatsink in place under dynamic loading. The heatsink clip must be designed in a way that minimizes contact with the motherboard surface during clip attach to the retention mechanism (RM) tab features; the clip should not scrape and/or scratch the motherboard. All surfaces of the clip should be free of sharp edges to prevent injury to any system component or to the person performing the installation. Heatsink clips should not exert loads that exceed the processor and socket limits. Refer to the processor datasheet for processor package maximum loading specifications and to the socket design guidelines for socket maximum loading specifications.

7.2.2.9 Retention Mechanism Requirements

The heatsink retention clips for the processor require a retention mechanism (RM). There are no features on the 603-pin surface mount socket to directly attach a heatsink. Instead, a retention mechanism is used to provide an attachment location for heatsink retention clips.

Intel has determined through extensive mechanical characterization that the use of direct chassis attach of the processor retention mechanism can mitigate the risk of mechanical damage to the motherboard, processor, and other surface mounted components in mechanical shock or mechanical drop testing. However, direct chassis attach may not mitigate that risk for all chassis and/or motherboard configurations. Mechanical shock or mechanical drop testing followed by functional and visual quality checks are required for each chassis-motherboard configuration.

Intel's thermal solution reference design uses direct chassis attach of the processor retention mechanism. Intel recommends the use of 6-32 [x 3/8-1/2"] pan head or round head screw [4 each] for direct retention mechanism to chassis attach. The screw head must be less than 0.284" diameter and less than 0.190" height.

7.2.2.10 Heatsink Bypass Requirements

Airflow bypass around the top, bottom, and sides of the 1U heatsink should be minimized, if not eliminated in 1U heatsink designs. Due to the low profile of the fins, typical 1U heatsinks are very sensitive to bypass and will suffer performance degradation as bypass increases. The Intel reference 1U heatsink design uses a foam insert to reduce bypass at the top of the heatsink to zero. The bypass at the sides are limited to 2.5 mm [0.1 in] maximum. Refer to Section A-2 for more information on heatsink bypass.

7.2.2.11 EMI Ground Frame Requirements

Test results indicate that an EMI grounding frame is not necessary to reduce the electro-magnetic emissions from the processor. As a result, Intel has not enabled tooling for the EMI grounding frame. The grounding frame is an optional component of the Intel reference design and is presented in Appendix B of this document (Figure 31).

7.3 Environmental Reliability Requirements

The thermal solution assembly (including all of its components) shall be designed to meet the environmental reliability requirements as outlined in Table 5.

Table 5. Environmental Reliability Test Conditions

Test	Level
Mechanical Shock (board level)	50G, 11 ms, Trapezoidal, 3 drops in each of 6 directions (± X, ± Y, ± Z); see Figure 15 for clarification of directions
Vibration	5-500 Hz, 3.13g RMS, 10 min/axis

Test	Level
Temperature Cycling	-25°C to 100°C, 10-30°C/min ramp, 15 min dwell, 192 cycles
Temperature Humidity	95°C, 85% RH, 14 days
Bake Test	95°C, 16 days, nominal (<25%) RH

Intel has found that certain board configurations may not meet the 50G board shock requirement using the enabled retention components. This is highly dependent on board thickness, processor layout, and other system design parameters. System integrators should shock test a system at acceleration levels consistent with their environmental reliability requirements. Intel's recommendation for system level shock includes a 6-axis, 25G, trapezoidal waveform shock, two drops per axis, with velocity change dependent on the weight of package.

7.4 Other Requirements

7.4.1 Recycling Recommendation

It is recommended that any plastic component exceeding 25 grams must be recyclable as per the *European Blue Angel* recycling standards.

7.4.2 Safety Requirements

The processor heatsink shall be consistent with the manufacture of units that meet the following safety standards:

> UL Recognition-approved for flammability at the system level –
> all mechanical-enabling components must be a minimum UL94V-0 approved.

7.4.3 Agency Requirements

All edges should not be sharp when tested per UL 1439.

7.5 Intel Reference Designs for Enabled Components

The figures in Appendix B present the Intel reference designs for the heatsinks, heatsink clips, EMI grounding frame, and the retention mechanism. Supplier contact information and mechanical CAD models of these components are available at http://developer.intel.com.

7.5.1 Reference Heatsinks for the 2U+ Form Factors

Intel has enabled multiple reference heatsinks for the Intel Xeon processor and Intel Xeon processor with 512 KB L2 cache in the 2U+ form factors.

- A copper base heatsink with soldered folded aluminum fins for the Intel Xeon processor.
- An aluminum base heatsink with both copper and aluminum fins crimped to the base for the Intel Xeon processor with 512 KB L2 cache for frequencies up to and including 2.8 GHz. The aluminum fins are shorted in length in the direction of airflow and is compatible with the processor wind tunnel (Section 8.2) , as shown in Figure 36 in Appendix B.
- A copper base extended performance heatsink with aluminum fins crimped to the base for the Intel Xeon processor with 512 KB L2 cache for frequencies greater than 2.8 GHz, as shown in Figure 37 in Appendix B.

Table 6 summarizes the reference heatsinks and includes additional details on heatsink features. Refer to the Intel part numbers provided in Table 6 when ordering heatsinks from enabled suppliers. A list of enabled suppliers along with contact information is available on http://developer.intel.com.

Note that the Intel Xeon processor reference heatsink is fully compatible with the Intel Xeon processor with 512 KB L2 cache. However, the Intel Xeon processor with 512 KB L2 cache requires the use of the Intel Xeon processor with 512 KB L2 cache reference heatsink or extended performance heatsink to meet thermal specifications.

Table 6. Processor Reference 2U+ Heatsinks

Attributes	Reference Heatsinks		
	Intel® Xeon™ Processor	Intel Xeon Processor with 512 KB L2 Cache	Intel Xeon Processor with 512 KB L2 Cache (Extended Performance)
Intel Part Number	751852	A53376	A99446
Heatsink base	Copper	Aluminum	Copper
Nominal Base thickness	6.35 mm [0.25 in]	6.35 mm [0.25 in]	7.0 mm [0.28 in]
Heatsink fins	Aluminum	Aluminum and Copper	Aluminum
Number of fins	32	32 total (12 Al, 20 Cu)	32
Recommended TIM	Shin-Etsu* G749	Shin-Etsu G751	Shin-Etsu G751
Recommended TIM dispense weight	250 mg	400 mg	400 mg
Case to local ambient Thermal resistance [Mean + 3sigma Ψ_{ca} (°C/W)]	0.42	0.40	0.33

Note: All heatsinks are compatible with the enabled clip and retention mechanism and conform to component keep-out zones documented in the processor platform design guidelines.

7.5.2 Reference Heatsink for the 1U Form Factor

The Intel reference heatsink design for the 1U form factor consists of an all copper passive heatsink with 32 fins based on crimped-fin technology, as shown in Figure 27 in Appendix B. A Mylar* backed foam bypass limiter will be attached to the reference heatsink to achieve zero bypass at the top of the heatsink. Shin-Etsu G751 thermal grease is the thermal interface material for the reference heatsink. This reference heatsink is intended for use with the Intel Xeon processor with 512 KB L2 cache at only the frequencies specified in Intel's 1U Front End Server roadmap. Contact your Intel Field Sales representative for the latest roadmap.

Table 7 summarizes the case to ambient thermal resistance, Ψ_{CA}, of the Intel 1U reference.

Table 7. Thermal Resistance Summary of 1U Intel Reference Heatsink

Volumetric Airflow (CFM)	Thermal Resistance, Ψ_{ca} (°C/W), mean + 3σ
10.0	0.53

Based on these thermal resistance values, the reference heatsink does not meet the datasheet specifications at typical server design constraints (i.e. 45°C processor ambient temperature and 10 CFM airflow). However, the reference heatsink *will* meet the datasheet specifications at 1U specific design constraints. Examples of 1U specific constraints are listed in Table 8.

Table 8. Example 1U Specific System Design Constraints

Volumetric Airflow (CFM)	Maximum Local Ambient Temperature (°C)
9.0	36.0
10.0	38.0

The 1U specific design constraints in Table 8 are challenging to achieve in typical 1U front-end servers intended for the value segment. Extensive upgrades to fans, blowers, and ducting may be required to convert current 1U chassis to provide this level of thermal performance.

System integrators that wish to see no noticeable Thermal Control Circuit (TCC) activation should design their systems to constraints listed in Table 8 and meet datasheet specifications. For integrators that are willing to accept a small performance tradeoff for cost, Intel has determined that the use of the reference heatsink in typical server environments will result in a very low probability of TCC activation.

Table 9summarizes the reference heatsinks and includes additional details on heatsink features.

Table 9. Processor Reference 1U Heatsink

Attributes	Reference Heatsink
	Intel® Xeon™ Processor with 512 KB L2 cache (1U Form Factor)
Intel Part Number	A78738
Heatsink base	Copper
Nominal Base thickness	6.35 mm [0.25 in]
Heatsink fins	Copper
Number of fins	32

Attributes	Reference Heatsink
	Intel® Xeon™ Processor with 512 KB L2 cache (1U Form Factor)
Recommended TIM	Shin-Etsu* G751
Recommended TIM dispense weight	400 mg
Case to local ambient Thermal resistance [Mean + 3sigma Ψ_{ca} (°C/W)]	0.53

7.5.3 Reference Heatsink Clips

The Intel reference design heatsink clip will attach to the heatsink base via the grooves at each end of the base. The reference design heatsink clip is latched to the reference design RM clip tabs, one at each end of the RM.

The clip design for the FC-mPGA2 package will differ from the clip for the INT-mPGA package to account for changes in package height and maintain a consistent load on the heatsink and TIM, as shown in Figure 27 through Figure 29 in Appendix B. System integrators need to ensure that the proper clips will be installed on the correct processor package. The FC-mPGA2 clips will have a hole punched in the area near the center window. See Figure Figure 17 for a comparison of the INT-mPGA and FC-mPGA2 clips.

The clips may be susceptible to deformation during any rework or upgrade procedure where the heatsink assembly is disassembled. Intel's clip design was validated with unused clips that were not subjected to an assembly-disassembly cycle. The system integrator should exercise caution in re-using clips that have experienced one or more assembly-disassembly cycles.

The reference designs accommodates the vertical height of the processor, as specified in the processor datasheet, and the vertical height of the 603-pin socket, as specified in the *603-Pin Socket Design Guidelines*. The Intel reference design heatsink clips will apply a total load on the thermal interface material of approximately 25 lbf.

The clips may be susceptible to deformation during any rework or upgrade procedure where the heatsink assembly is disassembled. Intel's clip design was validated with unused clips that were not subjected to an assembly-disassembly cycle. The system integrator should exercise caution in re-using clips that have experienced one or more assembly-disassembly cycles.

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Figure 17. Clip Comparison

INT-mPGA Package Clip

FC-mPGA2 Package Clip

7.5.4 Reference Retention Mechanisms

Intel’s reference design for the heatsink retention mechanism (RM) is shown in four drawing sheets starting with Figure 32 in Appendix B. Refer to Section 7.2.2.9 for design requirements pertaining to the enabled RMs.

7.5.5 Bypass Limiting Gasket for the 1U Heatsink

A thin piece of polyimide foam backed by Mylar and adhesive is part of Intel’s 1U reference thermal solution design. The foam serves to block airflow between the top of the heatsink fins and the duct surface above the heatsink. The foam is compliant enough to accommodate changes in heatsink height due to height differences between the INT-mPGA and FC-mPGA2 processor packages. The Mylar side contains adhesive which will adhere to the heatsink fins. top surfaces. Refer to Figure 11-15 for a drawing of the bypass limiting gasket.

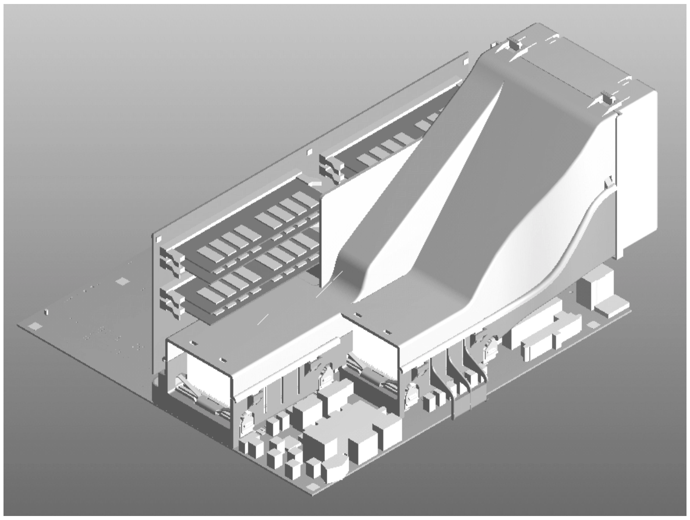
8 *Enabled Ducting Solutions*

Intel has enabled two ducting solutions for the 2U+ heatsink designs, the dual processor fan duct (DPFD) and the processor wind tunnel (PWT). These duct designs are point solutions presented here to assist the system integrator in developing a system specific ducting solution. They are not Intel reference solutions.

8.1 Dual Processor Fan Duct (DPFD)

The DPFD is available in two configurations. An exhausting design intended for an extended-ATX form factor and a pressurizing design more suitable for some SSI form factors. The exhausting DPFD consists of a two piece plastic duct assembly combined with a 120 mm exhaust fan. It provides airflow management for one or two processors and additional subsystem components, including memory, chipsets, and voltage regulators. The pressurizing DPFD uses only the top duct piece and is more flexible in terms of motherboard processor layout. DPFD design advantages include reduced fan count, scalability, and high thermal performance. Figure 18 shows a DPFD in an exhausting configuration.

Figure 18. Dual Processor Fan Duct (Exhausting Design)



Extensive guidelines for designing a dual processor duct are found in *Guidelines for Duct Design for Dual Processor Platform Applications,* Rev. 1.0. Topics include acoustic, structural, and mechanical design considerations, calculating and minimizing system pressure drop, heatsink bypass effects, and fan requirements. This document is available through your Intel Field Sales representative.

8.2 Processor Wind Tunnel (PWT)

The PWT is a low cost, high performance ducting solution that can be configured to fit extended-ATX/SSI/WTX chassis without requiring modifications. The PWT is an efficient application of existing off-the-shelf fan technology. Configurations with multiple fans are possible to enable redundancy in system cooling solutions.

System board layout is critical in implementing PWTs as part of a system thermal solution. Component placement can force special PWT implementations. For instance, some board layouts may cause one of the PWTs to extend beyond the board outline in a DP system. Other layouts may force one of the PWTs to be pressure cooled and the other vacuum cooled in order to retain system airflow direction.

A basic PWT configuration shown in Figure 19 and Figure 20 will be supplied with the boxed Intel Xeon processors and supported motherboards. The PWT assembly includes three plastic components (a processor shroud, a fan housing, and an end cap), a heatsink, two heatsink spring clips, a 60x25 mm fan, and a unique processor retention mechanism (RM). The PWT RM provides additional features not currently present on the standard Intel Xeon family processor RM. These features are necessary to anchor the PWT assembly to the RM.

Figure 19. Processor Wind Tunnel

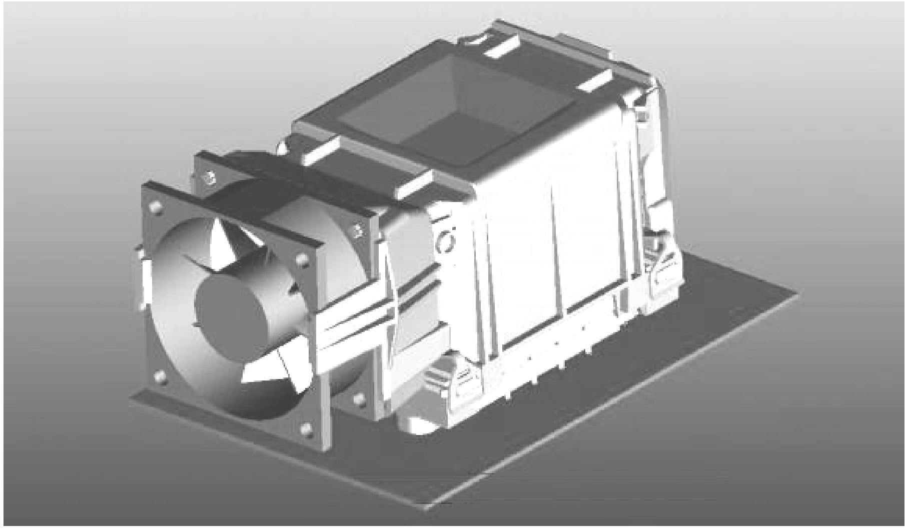


Figure 20. PWT Alternate View

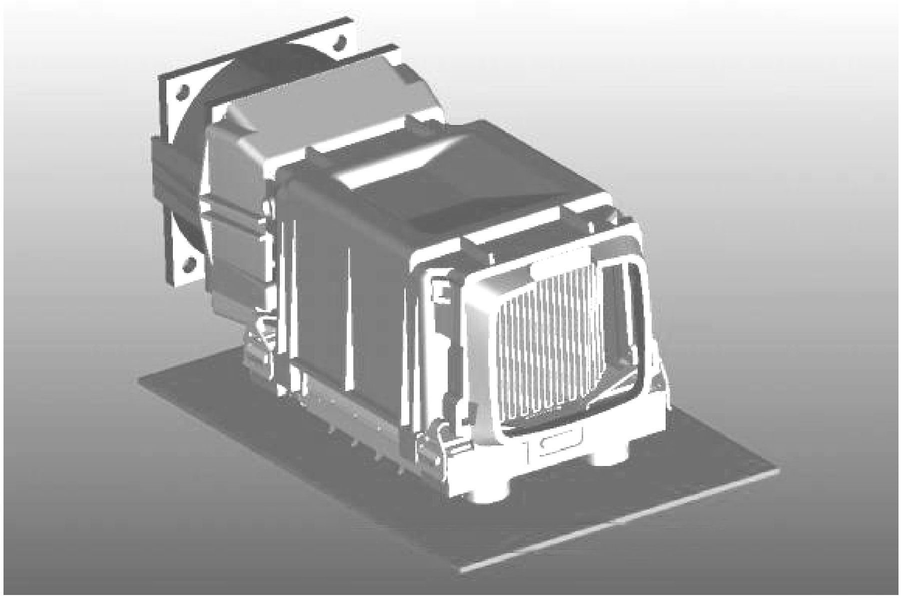


Figure 21. PWT with Duct

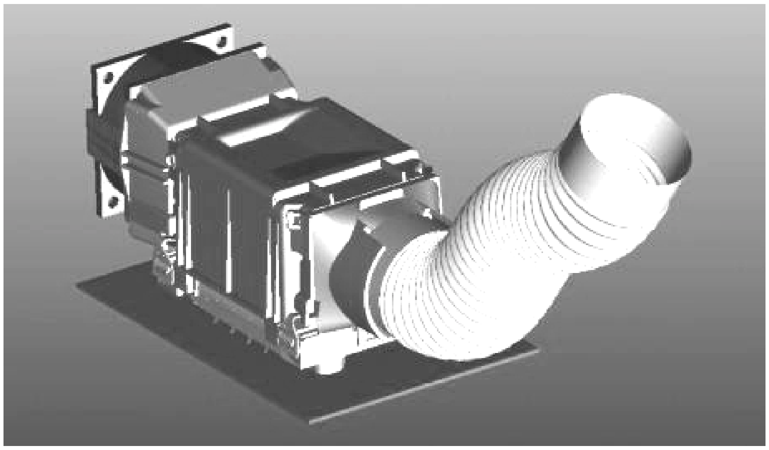
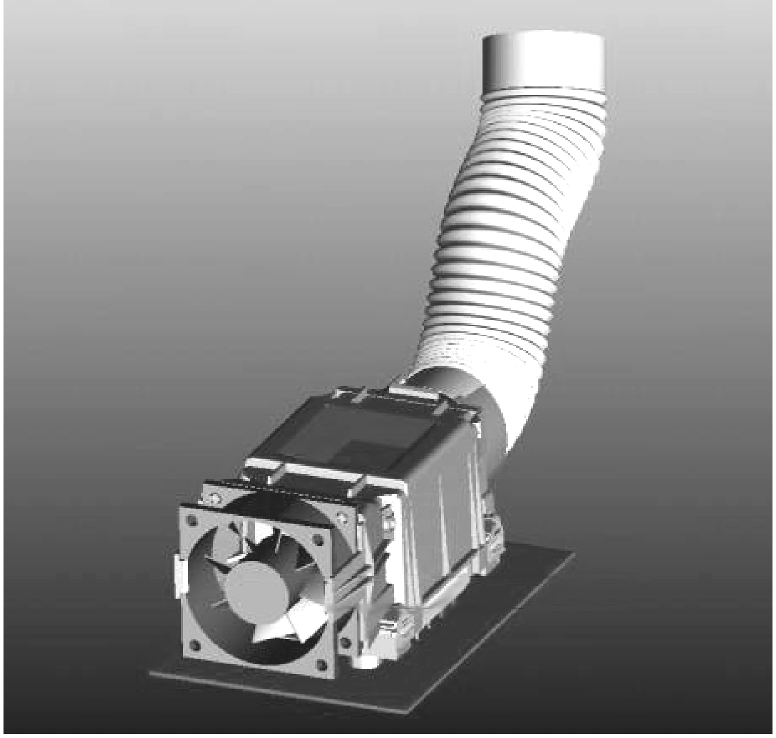


Figure 22. PWT with Duct Alternate View



The PWT cooling system is extremely versatile in that it can be configured to provide vacuum or pressure cooling. In addition, a variety of PWT end caps are available that provide a wide range of thermal options to the system integrator. All PWT end caps are symmetrical; therefore thermal redundancy can be achieved in environments that provide adequate PWT clearance. An optional PWT end cap, the hose adaptor, is currently available but not shipping with the boxed Intel Xeon processor. This component makes it possible for the PWT to provide $T_{ambient-external}$ via a flexible expandable ducting hose (Figure 21 and Figure 22) to provide substantially cooler ambient air directly to the processor heatsink. This option is particularly useful for heavily loaded systems generating high internal ambient temperatures. The hose adaptor and expandable ducting hose are currently available, but the distribution model for these parts is under evaluation (updates will be available at a future date at http://program.intel.com).

The PWT makes it possible for many 60 x 25 mm tube-axial fans to meet the airflow requirements of Intel's high performance processors.

9 Conclusion

As the complexity of today's microprocessors continues to increase, so do the power dissipation requirements. Care must be taken to ensure that the additional power is properly dissipated. Heat can be dissipated using passive heatsinks, fans and/or active cooling devices. Incorporating ducted airflow solutions into the system thermal design can yield additional margin.

The processor has thermal management logic integrated into the processor silicon as well as on-package thermal sensor with SMBus interface. This circuit may be configured to automatically limit the processor temperature through the use of the thermal monitor feature. At a factory-calibrated temperature, the processor will periodically stop the internal clocks in order to reduce power consumption and cool down the processor. Various registers and bus signals are available to monitor and control the processor thermal status.

A chassis cooling solution designed to the thermal design power listed in the processor datasheet will adequately cool the processor to a level where activation of the thermal monitor feature is either very rare or non-existent. Various levels of performance vs. cooling capacity are available and must be understood before designing a chassis. The OEM has the option to design software to monitor and control the processors thermal capabilities as part of the total system thermal solution.

The size of the heatsink and the output of the fan can be varied to balance size, cost, and space constraints with acoustic noise. This document has presented the conditions and requirements for properly designing a heatsink solution for an Intel Xeon processor-based system. Properly designed solutions provide adequate cooling to maintain Intel Xeon processor thermal specifications. This is accomplished by providing a low local-ambient temperature and creating a minimal thermal resistance to that local-ambient temperature. Ducting cool external air is highly recommended as a means to lower total cooling solution cost and complexity. By maintaining the processor's case temperature at the values specified in the processor datasheet, a system designer can be confident of proper functionality, performance, and reliability of these processors.

A Designing for Thermal Performance

In designing for thermal performance, the goal is to keep the processor(s) within the operational thermal specifications. Failure to do so will shorten the life of the processor(s) and potentially cause erratic system behavior. The thermal design is required to ensure these operational thermal specifications are maintained. The heat generated by components within the chassis must be removed to provide an adequate operating environment for both the processor and other system components. Moving air through the chassis transports the heat generated by the processor and other system components out of the system, while bringing in air from the external ambient environment.

A.1 Airflow Management

It is important to manage the amount of air that flows within the system as well as how it flows in order to maximize the amount of cool air that flows over the processor. System airflow can be increased by adding one or more fans to the system or by increasing the output (increasing the speed or size) of an existing system fan(s). Managing the local airflow direction using baffles or ducts can also increase local airflow. An important consideration in airflow management is the temperature of the air flowing over the processor(s). Heating effects from chipset, voltage regulators, add-in boards, memory and disk drives greatly reduce the cooling efficiency of this air, as does recirculation of warm interior air through the system fan. Care must be taken to minimize the heating effects of other system components, and to eliminate warm air circulation.

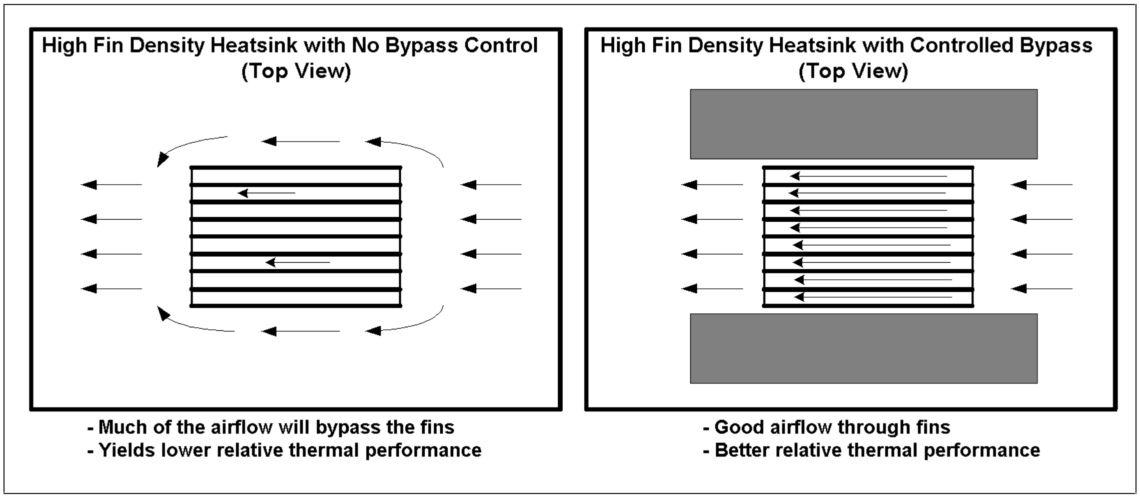
For example, a clear air path from the system fan(s) to the external system vents will enable the warm air from the processor(s) to be efficiently exhausted out of the system. If no air path exists across the processor(s), the heat generated by the processor(s) will not be removed from the system, resulting in localized heating ("hot spots") around the processors. Heatsink fin designs must be aligned with the direction of the airflow.

Many multi-processor system designs will have one processor positioned in front of another processor in the airflow. Without airflow management the second processor will see an increased ambient inlet temperature of about 10-15ºC, depending on the exact layout due to this “thermal shadow” effect.

A.2 Bypass

Bypass is the distance around the heatsink where air may travel without passing through the fins of the heatsink. A heatsink will have infinite bypass if it is sitting in free space. A duct or other device (such as a hard drive), located 5.1mm [0.2 in] from the outer edges of the heatsink, is said to have a bypass of 5.1 mm. A smaller bypass forces more air to pass through the fins of the heatsink, instead of around the heatsink. This is especially important as the heatsink fin density increases. The higher the fin density, the more resistance the heatsink poses to the air and the more likely the air will travel around the heatsink instead of through it unless the bypass is small. Air traveling around the heatsink will have little effect on cooling the processor. Note that as air bypass is decreased, the pressure required to deliver the same amount of volumetric airflow will increase. Pressure drop across the heatsink will also rise as more fins are added, and/or if fin thickness increases as well. Refer to Figure 23 for an illustration on bypass control.

Figure 23. Heatsink Bypass Examples



A.3 Heatsink Solutions

One method used to improve thermal performance is to increase the surface area of the device by attaching a metallic heatsink. To maximize the heat transfer, the thermal resistance from the heatsink to the air can be reduced by maximizing the airflow through the heatsink fins as well as by maximizing the surface area of the heatsink itself. As faster processors become available with higher power dissipation, the typical aluminum extruded heatsink may not be sufficient to cool the entire range of thermal design power. More advanced cooling techniques will likely be required, such as copper base, vapor chamber base, and/or folded fin heatsink with or without an integrated fan.

A.4 Thermal Interface Management

To optimize the heatsink design, it is important to understand the impact of factors related to the interface between the processor and the heatsink base. Specifically, the bond line thickness, interface material area and interface material thermal conductivity should be managed to realize the most effective thermal solution.

A.4.1 Bond Line Management

Any gap between the processor's heat spreader and the heatsink base will impact thermal solution performance. The larger the gap between the two surfaces, the greater the thermal resistance. The thickness of the gap is determined by the flatness of both the heatsink base and the integrated heat spreader, plus the thickness of the thermal interface material (i.e. thermal grease) used between these two surfaces and the clamping force applied by the heatsink attach clip(s).

A.4.2 Interface Material Area

The size of the contact area between the processor and the heatsink base will impact the thermal resistance. There is, however, a point of diminishing returns. Unrestrained incremental increases in thermal interface material area do not translate to a measurable improvement in thermal performance.

A.4.3 Interface Material Performance

Two factors impact the performance of the interface material between the processor and the heatsink base:

1. Thermal resistance of the material
2. Wetting/filling characteristics of the material

Thermal resistance is a description of the ability of the thermal interface material to transfer heat from one surface to another. The higher the thermal resistance, the less efficient the interface is at transferring heat. The thermal resistance of the interface material has a significant impact on thermal performance. The higher the thermal resistance, the higher the temperature drop across the interface and the more efficient the thermal solution (i.e. heatsink) must be to achieve the desired cooling.

The wetting or filling characteristic of the thermal interface material is its ability, under the load applied by the heatsink attach clips, to spread and fill the gap between the processor and the heatsink. Since air is an extremely poor thermal conductor, the more completely the interface material fills the gaps, the lower the temperature drop across the interface. In this case, thermal interface material area also becomes significant; the larger the desired thermal interface material area, the higher the force required to spread the thermal interface material.

Intel has determined through thermal characterization that it may be challenging to meet the thermal performance targets with the use of phase change thermal interface materials. The use of thermal grease in conjunction with high performance heatsink technologies (e.g. copper base folded fin) has been demonstrated to meet Intel thermal performance requirements. The use of thermal grease is recommended.

A.5 Fans

Fans are needed to move the air through the chassis. The acoustic noise level of a fan is usually directly related to the airflow rate of the fan. Maximum acceptable noise levels may limit the fan output or the number of fans selected for a system. By lowering the ambient temperature at the inlet of the heatsink (T_{LA}), lower airflow across the heatsink and thus slower fan speed can be attained to improve system acoustics. Utilization of ducting or baffles is one method to deliver lower T_{LA} and improve acoustics. See Section A.6.1 for more details regarding ducting

Fan heatsinks are one type of advanced solution that can be used to cool the processor. Due to the concern for reliability and redundancy, the current enabled reference design does not include fan heatsink cooling. However, all of the mechanical features are present for the OEM that wishes to use a fan heatsink assembly. High reliability fan heatsinks are becoming increasingly available, and including support for such a device in the system board may allow for increased flexibility in the cooling solution.

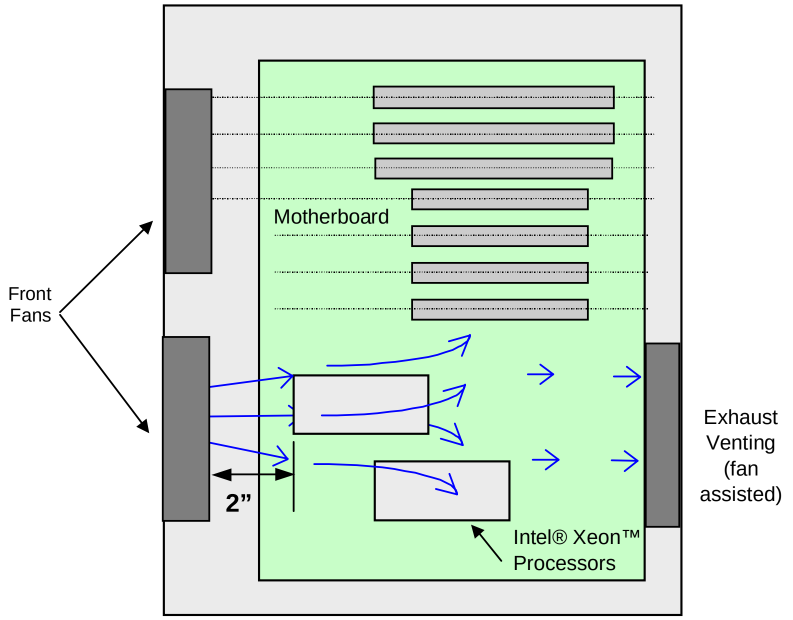
A.5.1 Placement

Proper placement of the fans can help ensure that the processor is being properly cooled. Because of the difficulty in building, measuring and modifying a mechanical assembly, models are typically developed and used to simulate a proposed prototype for thermal effectiveness to determine the optimum location for fans and vents within a chassis. Prototype assemblies can also be built and tested to verify if the system components and processor thermal specifications are met.

An intake air fan ideally is centered vertically and placed along one axis with respect to the processor and heatsink. The fan should also be approximately 50.8 mm [2.0 in] from the leading edge of the passive heatsink. Figure 24 shows the fan placement for a typical dual processor layout.

The system fans should be pulling in air from the exterior of the system, and flow directly onto the heatsink. Reduction in preheating of the heatsink airflow results in a degree for degree reduction in the processor case temperature with all other parameters remaining constant.

Figure 24. Fan Placement and Layout of a Dual-Processor System – Top View



A.5.2 Direction

If the fan(s) are not moving air across the heatsink, then little cooling can occur and the processor may operate above the specified temperature. Two possibilities exist for blowing air across the heatsink of the processor. Air can be blown horizontally, parallel to the baseboard, which blows the air through the length of the heatsink. The air stream can be blown vertically, perpendicular to the baseboard, or down into the heatsink. This may depend on the layout of other components on the board and/or within the chassis. Preferably the intake fan will blow through the heatsink lengthwise because the heatsink fins can be shorter in this case. Both of these factors are considerations when laying out components on the board and in the chassis.

The airflow should be directed with baffles or ducts to flow through the heatsink. This will increase the local flow through the heatsink and may eliminate the need for a second, larger, or higher speed fan.

In dual and quad processor systems the second or successive processor in line could receive preheated air. Simulation indicates there could be in excess of a 10ºC rise in air temperature through the first heatsink. This temperature rise makes it necessary to use baffles or ducts to provide cool air to the second processor and exhaust the first processor heated air.

A.5.3 Size and Quantity

It does not necessarily hold true that the larger the fan the more air it blows. A small blower using ducting might direct more air over the heatsink than a large fan blowing non-directed air over the heatsink. The following provide some guidelines for size and quantity of the fan(s).

The fan should be a minimum of 80 mm [3.15 in] square, with a minimum airflow of approximately 500 LFM (linear feet per minute) at the inlet to the heatsink. Ideally two (2) fans should be used. The intake air fan would blow directly into the processor and heatsink assembly, while a second fan, possibly the power supply would exhaust the air out of the system. For server products, multiple, redundant fans must also be considered for high-reliability systems. These recommendations may not apply if special system solutions, such as fan ducts, are used.

A.5.4 Venting

Intake ports should be placed at the front (user side) of the system to avoid any recirculation that can occur from the rear of a system with little wall clearance. Vent location placement should include consideration for cooling of processor and peripherals (drives and add-in cards). Intake venting directly in front of the intake fan is the most optimal location. The ideal design will provide airflow directly over the processor heatsink.

A.5.4.1 Placement

Exhaust venting in conjunction with the power supply exhaust fan is usually sufficient for smaller systems. However, depending on the number, location and types of add-in cards, exhaust venting may be necessary near the adapter cards. This should be modeled or prototyped for the optimum thermal potential. Hence, a system should be modeled for the worst case; i.e. all expansion slots should be occupied with typical add-in options.

A.5.4.2 Area and/or Size

The area and/or size of the intake vents should depend upon the size and shape of the fan(s). Adequate air volume must be obtained and thus will require adequate sized vents. Intake vents should be located in front of the intake fan(s) and adjacent to the drive bays. Venting should be approximately 50% to 60% open in the electromagnetic interference (EMI) containment area. Outside the EMI containment area, the open percentage can be greater if needed for aesthetic appeal (i.e. bezel/cosmetics). Caution should be exercised that venting is not excessive or poorly placed which can cause recirculation of warm exhaust air.

A.5.4.3 Vent Shape

Round, staggered pattern openings are best for EMI containment, acoustics and airflow balance.

A.6 Alternative Cooling Solutions

In addition to passive heatsinks, fan heatsinks and system fans, other solutions exist for cooling integrated circuit devices. For example, ducted blowers, heat pipes and liquid cooling are all capable of dissipating additional heat. Due to their varying attributes, each of these solutions may be appropriate for a particular system implementation. More information on this topic can be located on Intel's web site at http://developer.intel.com/.

A.6.1 Ducting

Ducts can be designed to isolate the processor(s) from the effects of system heating (such as add-in cards), and to maximize the processor cooling temperature budget. Air provided by a fan or blower can be channeled directly over the processor and heatsink, or split into multiple paths to cool multiple processors. This method can also be employed to provide some level of redundancy in a system requiring redundant capabilities for fault tolerance. This is accomplished by channeling air from two or more fans through the same path across a processor. Each fan, or each set of fans, must be designed to provide sufficient cooling in the event that the other has failed.

A.6.1.1 Ducting Placement

When ducting is to be used, it should direct the airflow evenly from the fan through the length of the heatsink. This should be accomplished, if possible, with smooth, gradual turns, as this will enhance the airflow characteristics. Sharp turns in ducting should be avoided. They increase friction and drag and will greatly reduce the volume of air reaching the processor heatsink. Duct placement should include cooling considerations for other heat dissipating devices. The system designer may want to include auxiliary cooling for other devices, such as voltage regulator modules, memory, etc., in the processor ducting design. If auxiliary cooling is not implemented, the system designer should ensure any duct design does not impede airflow to these devices.

A.7 System Components

A.7.1 Placement

Peripherals such as CD-ROMs, floppy drives, hard drives, VRMs, etc. can be placed to take advantage of a fan's movement of ambient air (by placing them near intake or exhaust fans or venting). Some add-in cards have a low tolerance for temperature rise. These components should be placed near additional venting if they are downstream of the processor to minimize an increase in their ambient temperature.

A.7.2 Power

Some types of drives, such as floppy drives, do not dissipate much heat, while others (e.g. read/write CD-ROM drives, SCSI drives) dissipate a great deal of heat. These hotter components should be placed near fans and/or venting whenever possible. The same can be said for some types of add-in cards. Some PCI cards are very low wattage (approximately 5 W) while others can be as high as 25 W, per the PCI specification. AGP graphics devices can dissipate up to 25 W per AGP revision 2.0 specifications while AGP Pro50 devices dissipate 25-50 W and AGP Pro110 devices dissipate 50-110 W per AGP Pro revision 1.1a specifications. Great care should be taken to ensure that these cards have sufficient cooling, while not adversely affecting the processor cooling.

A.8 Voltage Regulation Module (VRM) Considerations

A.8.1 Airflow and Local-ambient Temperature

Voltage regulation modules (VRMs) must also be considered in system cooling solutions. Because proper power delivery to the processor demands that the VRM be placed very close to the processors, local-ambient temperature for the VRM may be affected by the heating of the nearby processors. A typical VRM requires 400 LFM of airflow to remain within temperature specifications, assuming a local-ambient air temperature of 60ºC. VRM temperature specifications typically specify a maximum temperature at a physical location on the module. System thermal modeling should include the VRM(s) in the simulation to ensure they remain within specifications. VRM current delivery capability may be increased with efficient cooling.

B Mechanical Drawings

The following table lists the mechanical drawings included in this section.

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Heatsink Base Dimensions	62
Heatsink Volumetric Keep-in Zone (2U+ Form Factors)	63
Heatsink Volumetric Keep-in Zone (1U Form Factor)	64
Enabled Heatsink Clip for INT-mPGA Package (Sheet 1 of 2)	65
Enabled Heatsink Clip for INT-mPGA Package (Sheet 2 of 2)	66
Enabled Heatsink Clip for FC-mPGA2P Package (Sheet 1 of 1)	67
EMI Shield	68
Enabled Retention Mechanism (Sheet 1 of 4)	69
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Intel® Xeon™ Processor with 512 KB L2 Cache Heatsink (2U+)	73
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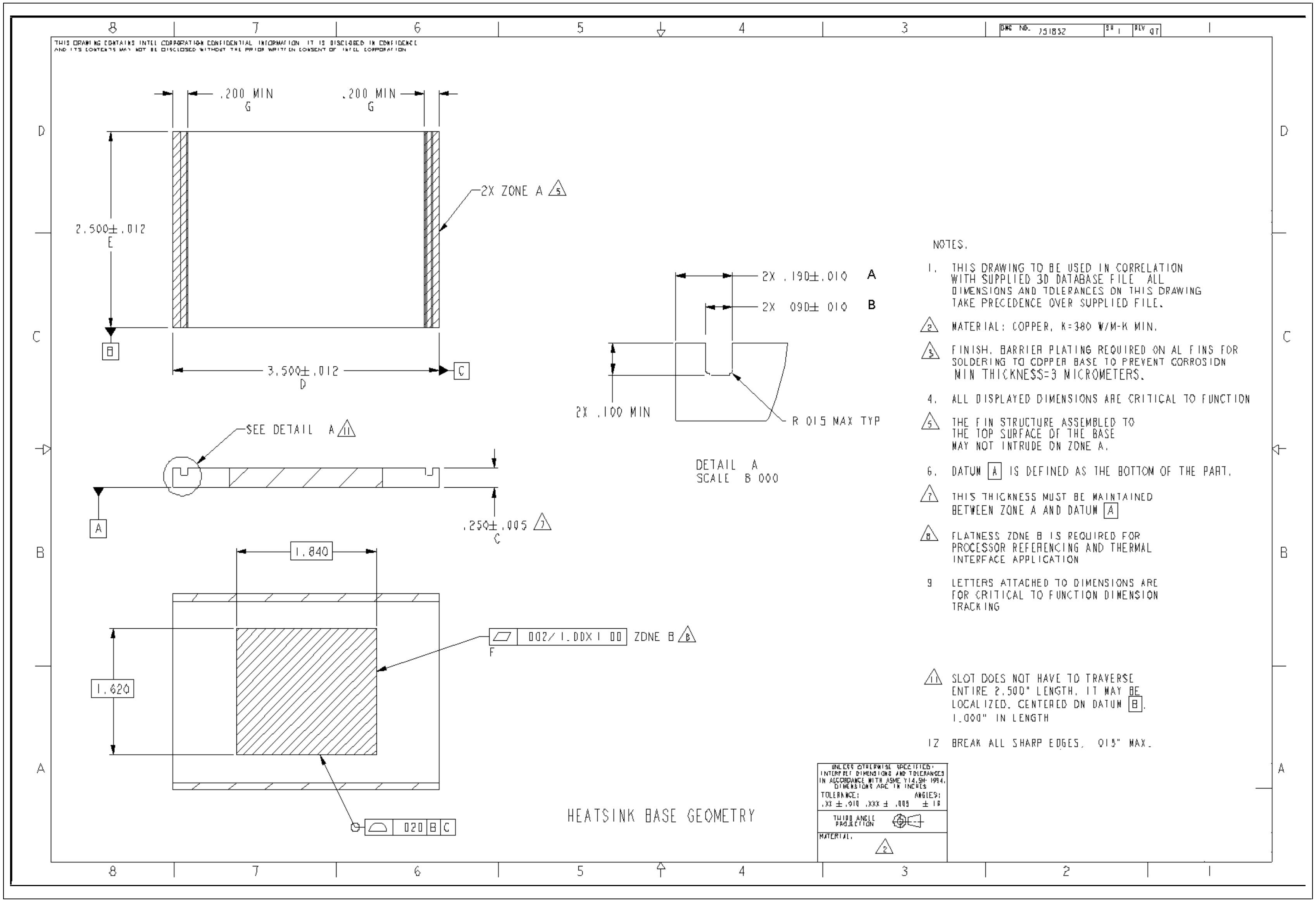
Intel® Xeon™ Processor with 512 KB L2 Cache Heatsink (1U)	75
Intel® Xeon™ Processor with 512 KB L2 Cache Heatsink (1U) Bypass Gasket	76

Figure 25. Heatsink Base Dimensions



NOTES.

1. THIS DRAWING TO BE USED IN CORRELATION WITH SUPPLIED 3D DATABASE FILE. ALL DIMENSIONS AND TOLERANCES ON THIS DRAWING TAKE PRECEDENCE OVER SUPPLIED FILE.

2. MATERIAL: COPPER, K=380 W/M-K MIN.

3. FINISH. BARRIER PLATING REQUIRED ON AL FINS FOR SOLDERING TO COPPER BASE TO PREVENT CORROSION MIN THICKNESS=3 MICROMETERS.

4. ALL DISPLAYED DIMENSIONS ARE CRITICAL TO FUNCTION

5. THE FIN STRUCTURE ASSEMBLED TO THE TOP SURFACE OF THE BASE MAY NOT INTRUDE ON ZONE A.

6. DATUM A IS DEFINED AS THE BOTTOM OF THE PART.

7. THIS THICKNESS MUST BE MAINTAINED BETWEEN ZONE A AND DATUM A

8. FLATNESS ZONE B IS REQUIRED FOR PROCESSOR REFERENCING AND THERMAL INTERFACE APPLICATION

9 LETTERS ATTACHED TO DIMENSIONS ARE FOR CRITICAL TO FUNCTION DIMENSION TRACKING

11. SLOT DOES NOT HAVE TO TRAVERSE ENTIRE 2.500" LENGTH. IT MAY BE LOCALIZED, CENTERED ON DATUM B. 1.000" IN LENGTH

12 BREAK ALL SHARP EDGES. .015" MAX.

Figure 26. Heatsink Volumetric Keep-in Zone (2U+ Form Factors)

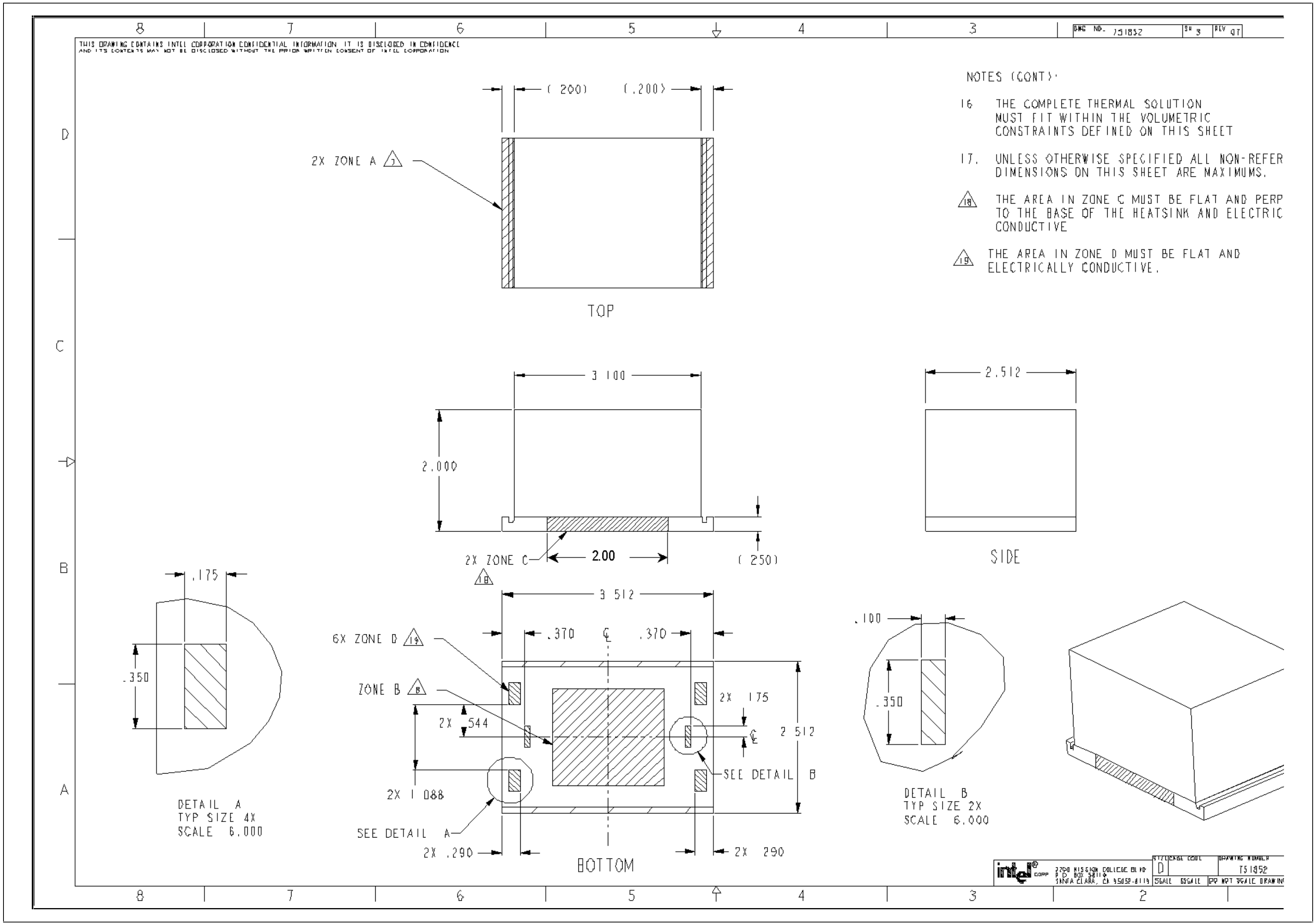


Figure 27. Heatsink Volumetric Keep-in Zone (1U Form Factor)

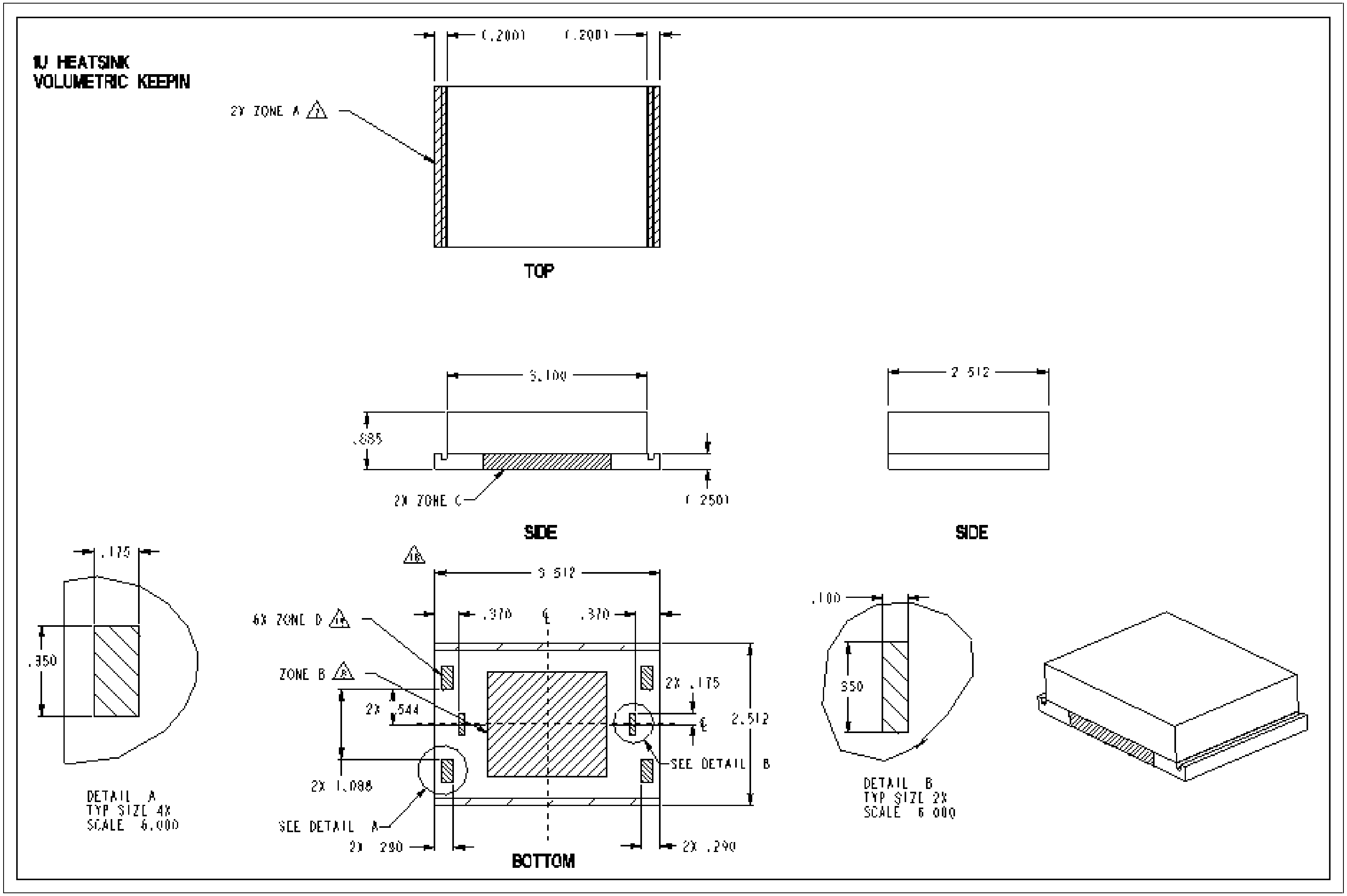
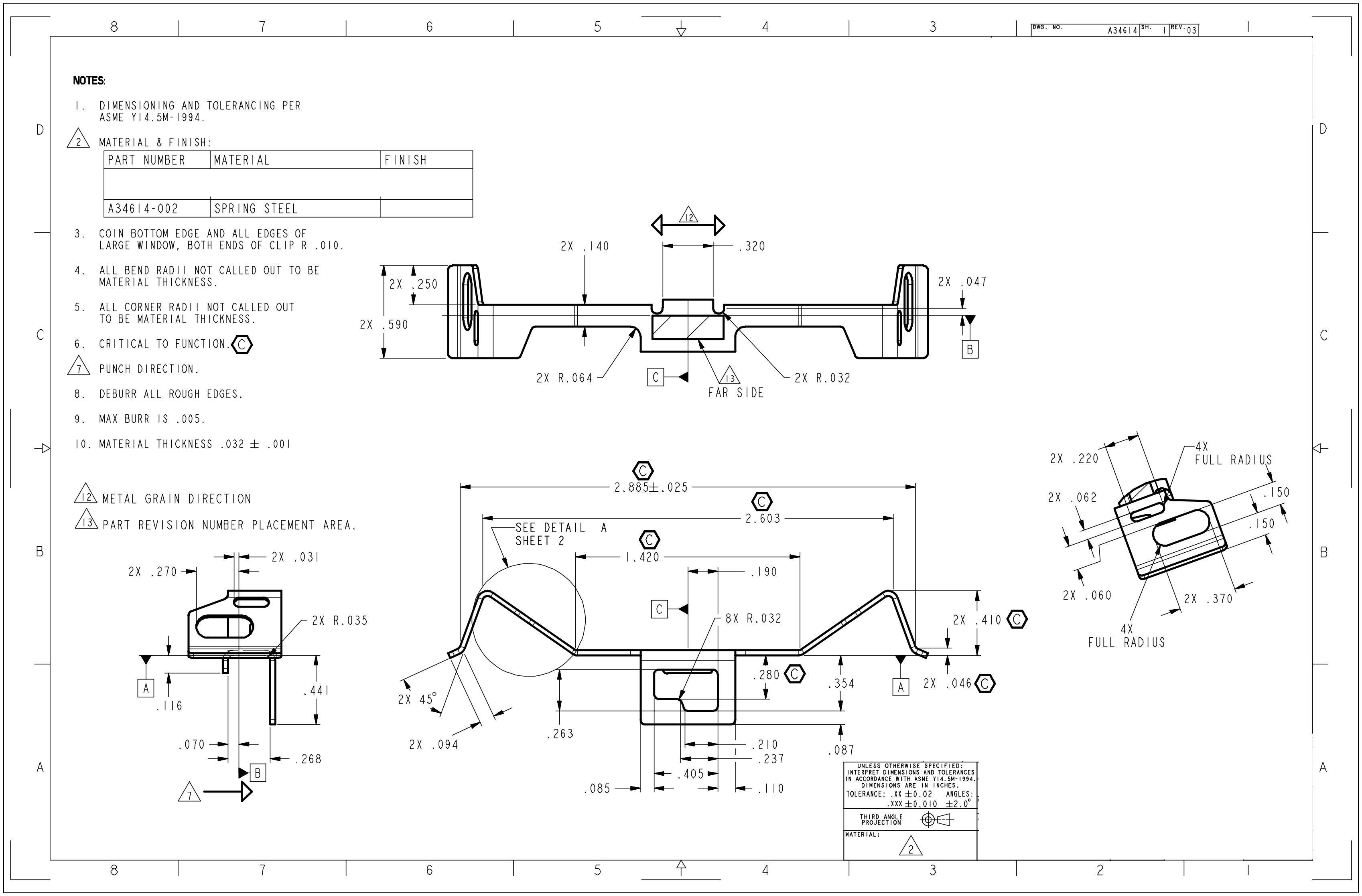


Figure 28. Enabled Heatsink Clip for INT-mPGA Package (Sheet 1 of 2)



NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.

2. MATERIAL & FINISH:

PART NUMBER	MATERIAL	FINISH
A34614-002	SPRING STEEL	

3. COIN BOTTOM EDGE AND ALL EDGES OF LARGE WINDOW, BOTH ENDS OF CLIP R .010.

4. ALL BEND RADII NOT CALLED OUT TO BE MATERIAL THICKNESS.

5. ALL CORNER RADII NOT CALLED OUT TO BE MATERIAL THICKNESS.

6. CRITICAL TO FUNCTION. Ⓒ

7. PUNCH DIRECTION.

8. DEBURR ALL ROUGH EDGES.

9. MAX BURR IS .005.

10. MATERIAL THICKNESS .032 ± .001

12 METAL GRAIN DIRECTION

13 PART REVISION NUMBER PLACEMENT AREA.

UNLESS OTHERWISE SPECIFIED:
INTERPRET DIMENSIONS AND TOLERANCES IN ACCORDANCE WITH ASME Y14.5M-1994.
DIMENSIONS ARE IN INCHES.
TOLERANCE: .XX ±0.02 ANGLES:
.XXX ±0.010 ±2.0°
THIRD ANGLE PROJECTION
MATERIAL: 2

Figure 29. Enabled Heatsink Clip for INT-mPGA Package (Sheet 2 of 2)

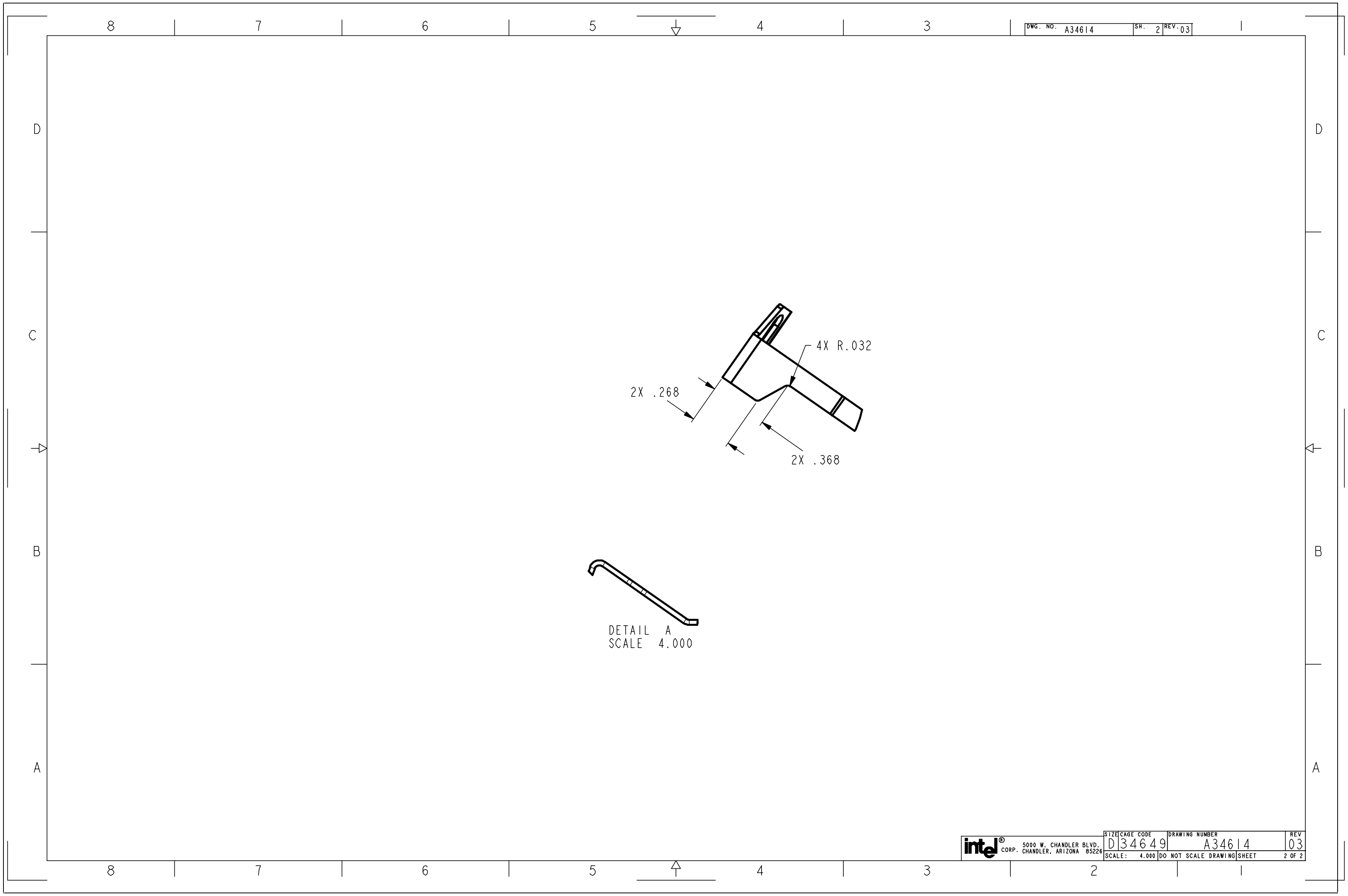


Figure 30. Enabled Heatsink Clip for FC-mPGA2P Package (Sheet 1 of 1)

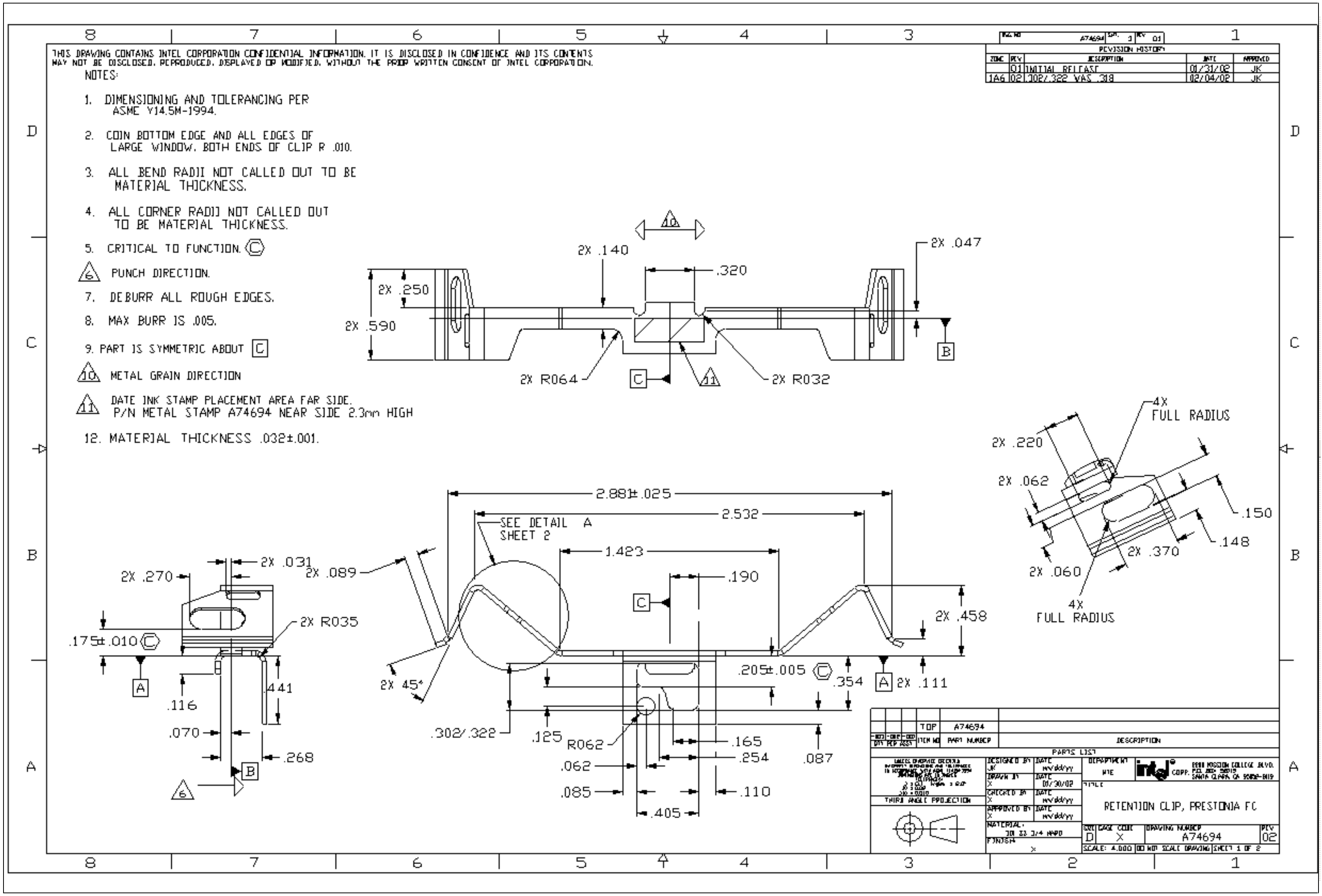


Figure 31. EMI Shield

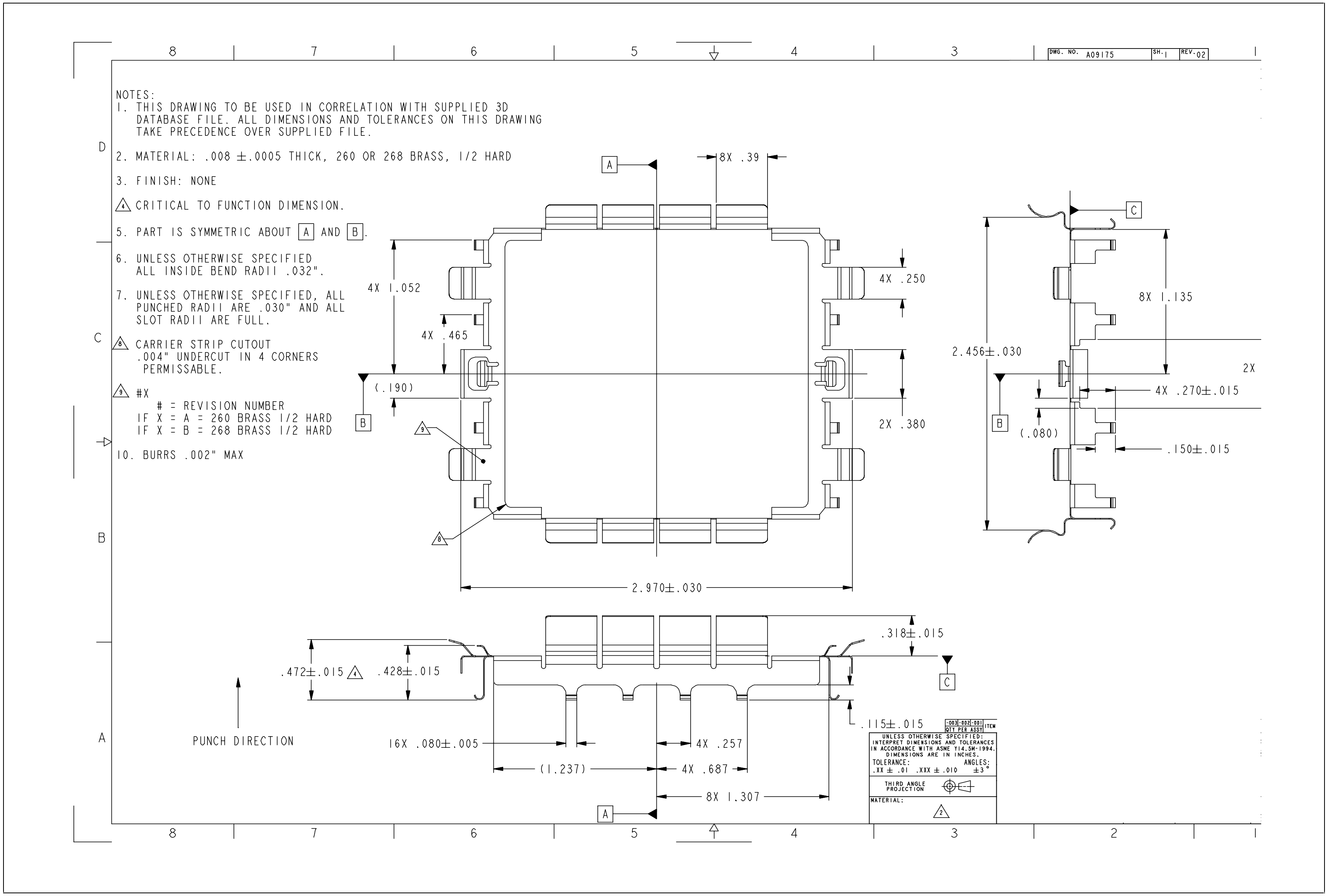
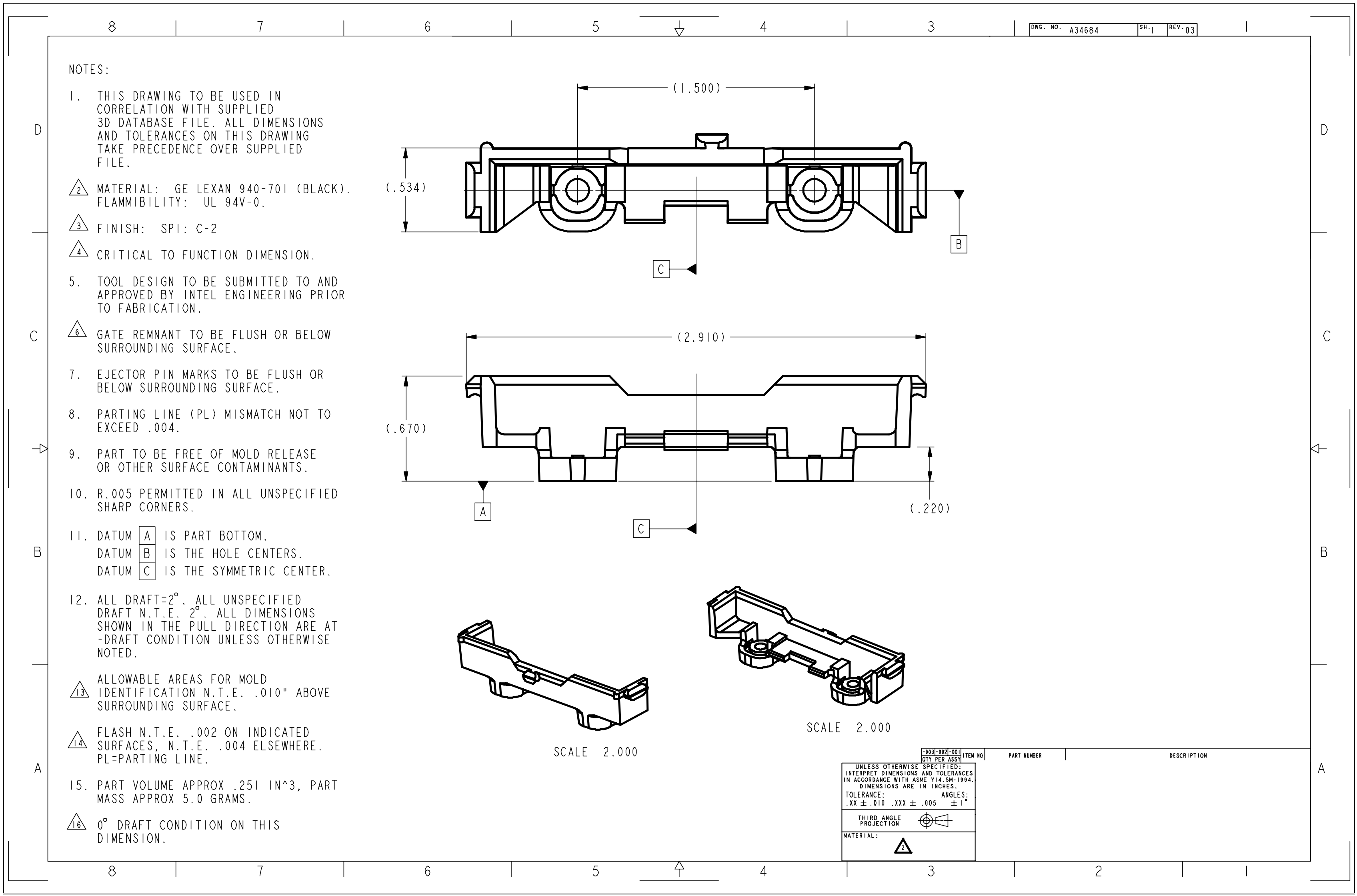


Figure 32. Enabled Retention Mechanism (Sheet 1 of 4)



NOTES:

1. THIS DRAWING TO BE USED IN CORRELATION WITH SUPPLIED 3D DATABASE FILE. ALL DIMENSIONS AND TOLERANCES ON THIS DRAWING TAKE PRECEDENCE OVER SUPPLIED FILE.

2. MATERIAL: GE LEXAN 940-701 (BLACK). FLAMMIBILITY: UL 94V-0.

3. FINISH: SPI: C-2

4. CRITICAL TO FUNCTION DIMENSION.

5. TOOL DESIGN TO BE SUBMITTED TO AND APPROVED BY INTEL ENGINEERING PRIOR TO FABRICATION.

6. GATE REMNANT TO BE FLUSH OR BELOW SURROUNDING SURFACE.

7. EJECTOR PIN MARKS TO BE FLUSH OR BELOW SURROUNDING SURFACE.

8. PARTING LINE (PL) MISMATCH NOT TO EXCEED .004.

9. PART TO BE FREE OF MOLD RELEASE OR OTHER SURFACE CONTAMINANTS.

10. R.005 PERMITTED IN ALL UNSPECIFIED SHARP CORNERS.

11. DATUM A IS PART BOTTOM.
DATUM B IS THE HOLE CENTERS.
DATUM C IS THE SYMMETRIC CENTER.

12. ALL DRAFT=2°. ALL UNSPECIFIED DRAFT N.T.E. 2°. ALL DIMENSIONS SHOWN IN THE PULL DIRECTION ARE AT -DRAFT CONDITION UNLESS OTHERWISE NOTED.

13. ALLOWABLE AREAS FOR MOLD IDENTIFICATION N.T.E. .010" ABOVE SURROUNDING SURFACE.

14. FLASH N.T.E. .002 ON INDICATED SURFACES, N.T.E. .004 ELSEWHERE. PL=PARTING LINE.

15. PART VOLUME APPROX .251 IN^3, PART MASS APPROX 5.0 GRAMS.

16. 0° DRAFT CONDITION ON THIS DIMENSION.

UNLESS OTHERWISE SPECIFIED:
INTERPRET DIMENSIONS AND TOLERANCES IN ACCORDANCE WITH ASME Y14.5M-1994.
DIMENSIONS ARE IN INCHES.
TOLERANCE: .XX ± .010 .XXX ± .005
ANGLES: ± 1°

-003	-002	-001	ITEM NO	PART NUMBER	DESCRIPTION
QTY PER ASSY					

Figure 33. Enabled Retention Mechanism (Sheet 2 of 4)

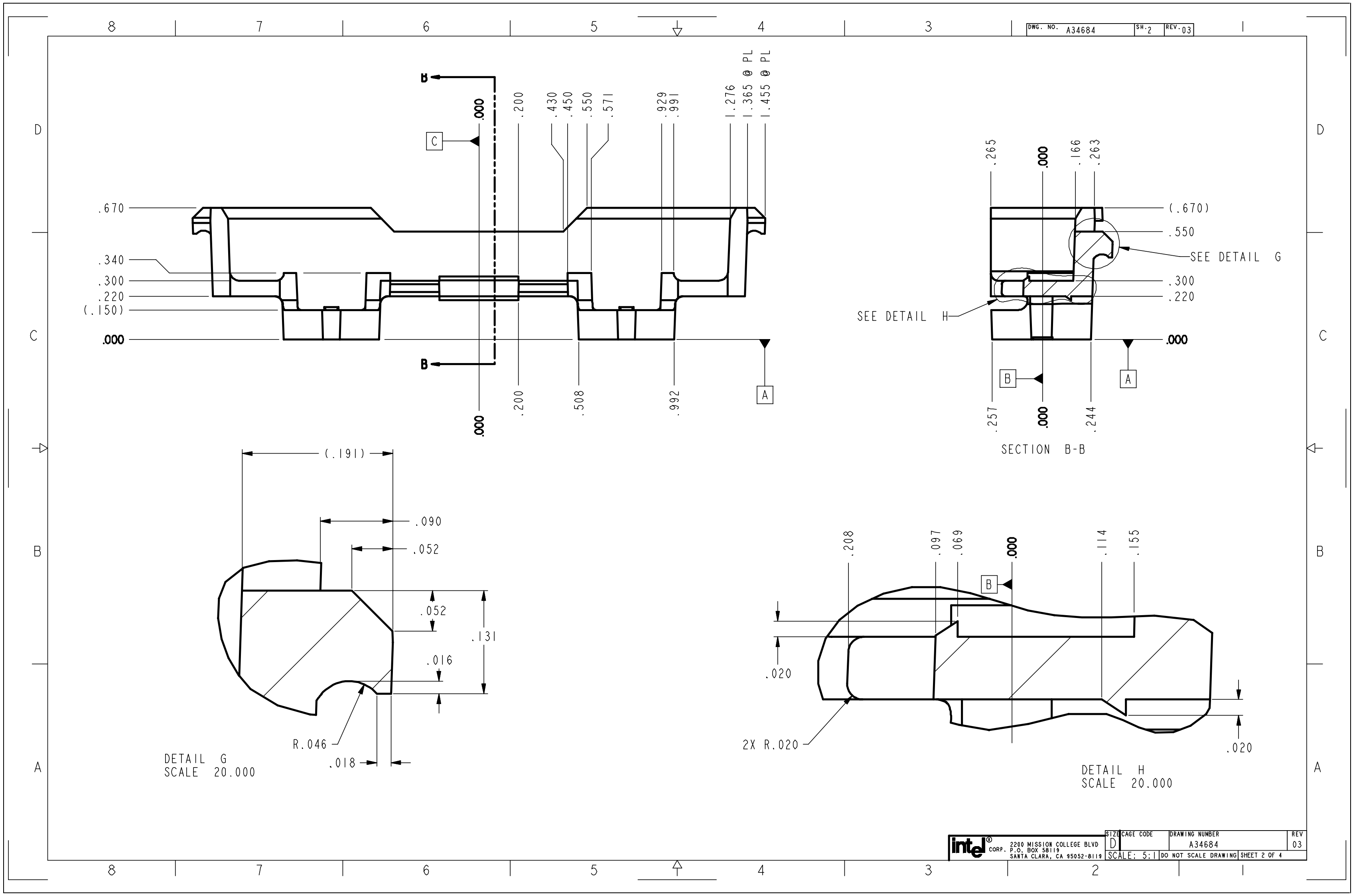


Figure 34. Enabled Retention Mechanism (Sheet 3 of 4)

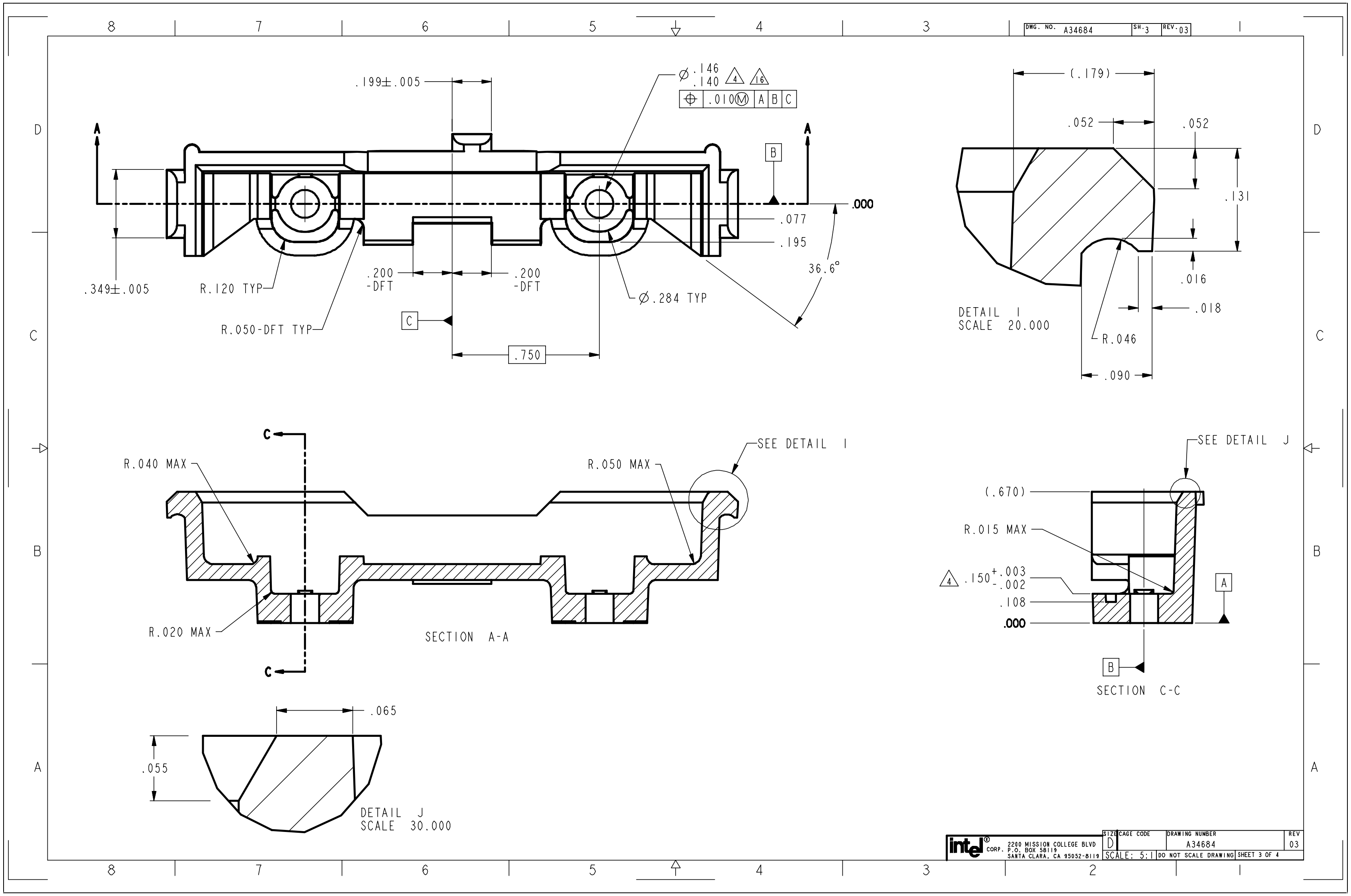


Figure 35. Enabled Retention Mechanism (Sheet 4 of 4)

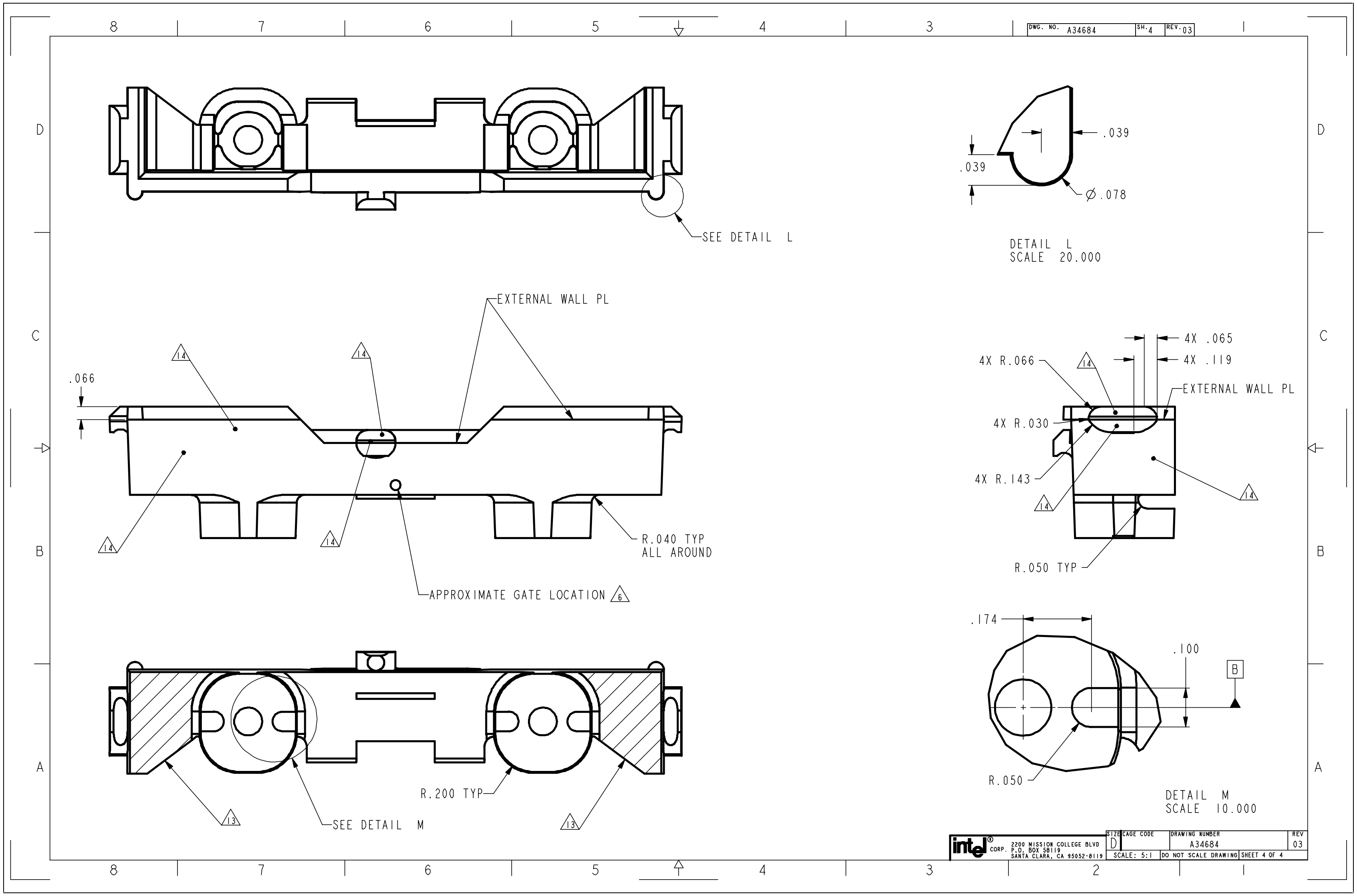
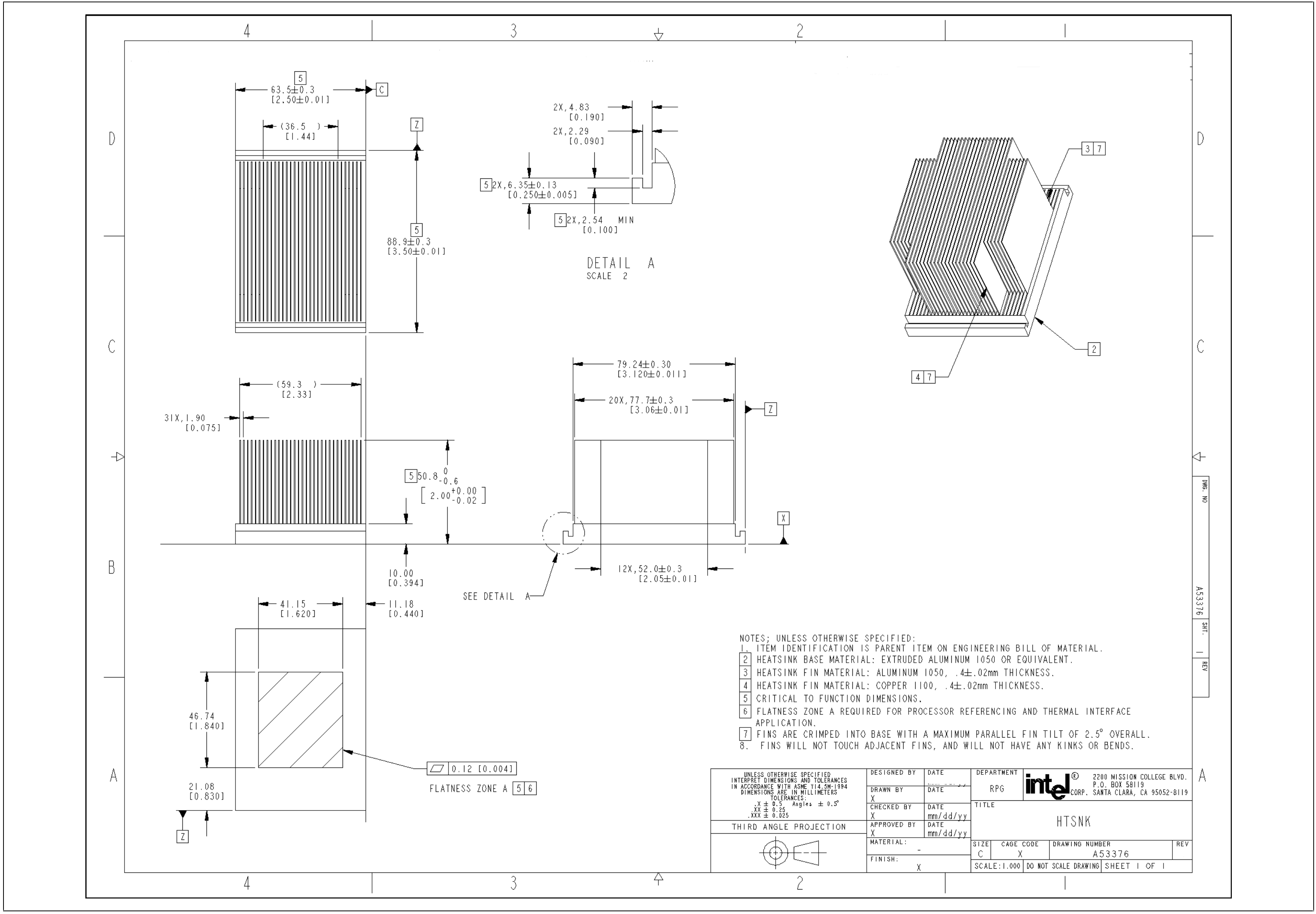


Figure 36. Intel® Xeon™ Processor with 512 KB L2 Cache Heatsink (2U+)



NOTES; UNLESS OTHERWISE SPECIFIED:

1. ITEM IDENTIFICATION IS PARENT ITEM ON ENGINEERING BILL OF MATERIAL.
2. HEATSINK BASE MATERIAL: EXTRUDED ALUMINUM 1050 OR EQUIVALENT.
3. HEATSINK FIN MATERIAL: ALUMINUM 1050, .4±.02mm THICKNESS.
4. HEATSINK FIN MATERIAL: COPPER 1100, .4±.02mm THICKNESS.
5. CRITICAL TO FUNCTION DIMENSIONS.
6. FLATNESS ZONE A REQUIRED FOR PROCESSOR REFERENCING AND THERMAL INTERFACE APPLICATION.
7. FINS ARE CRIMPED INTO BASE WITH A MAXIMUM PARALLEL FIN TILT OF 2.5° OVERALL.
8. FINS WILL NOT TOUCH ADJACENT FINS, AND WILL NOT HAVE ANY KINKS OR BENDS.

Figure 37. Intel® Xeon™ Processor with 512 KB L2 Cache Extended Performance Heatsink (2U+)

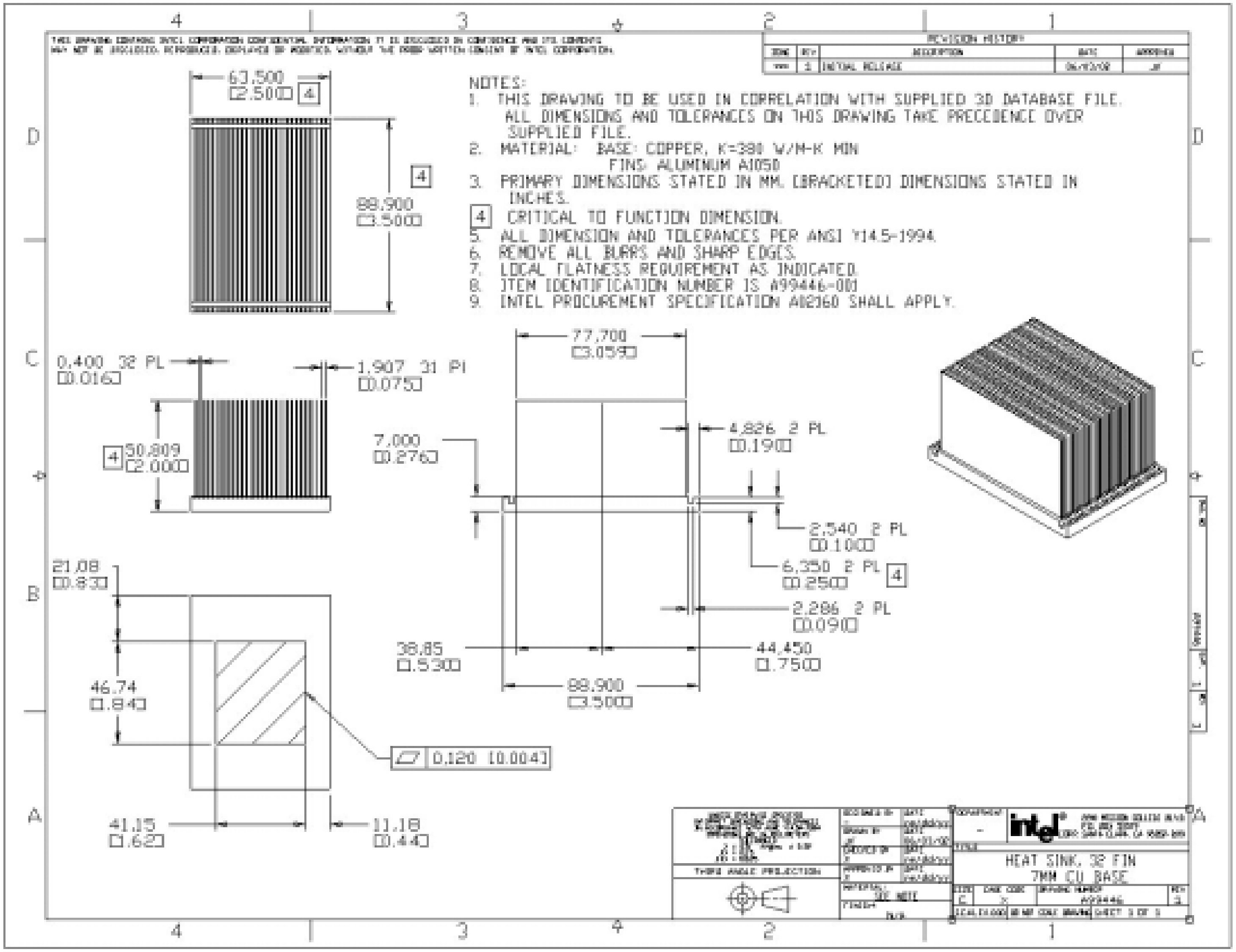
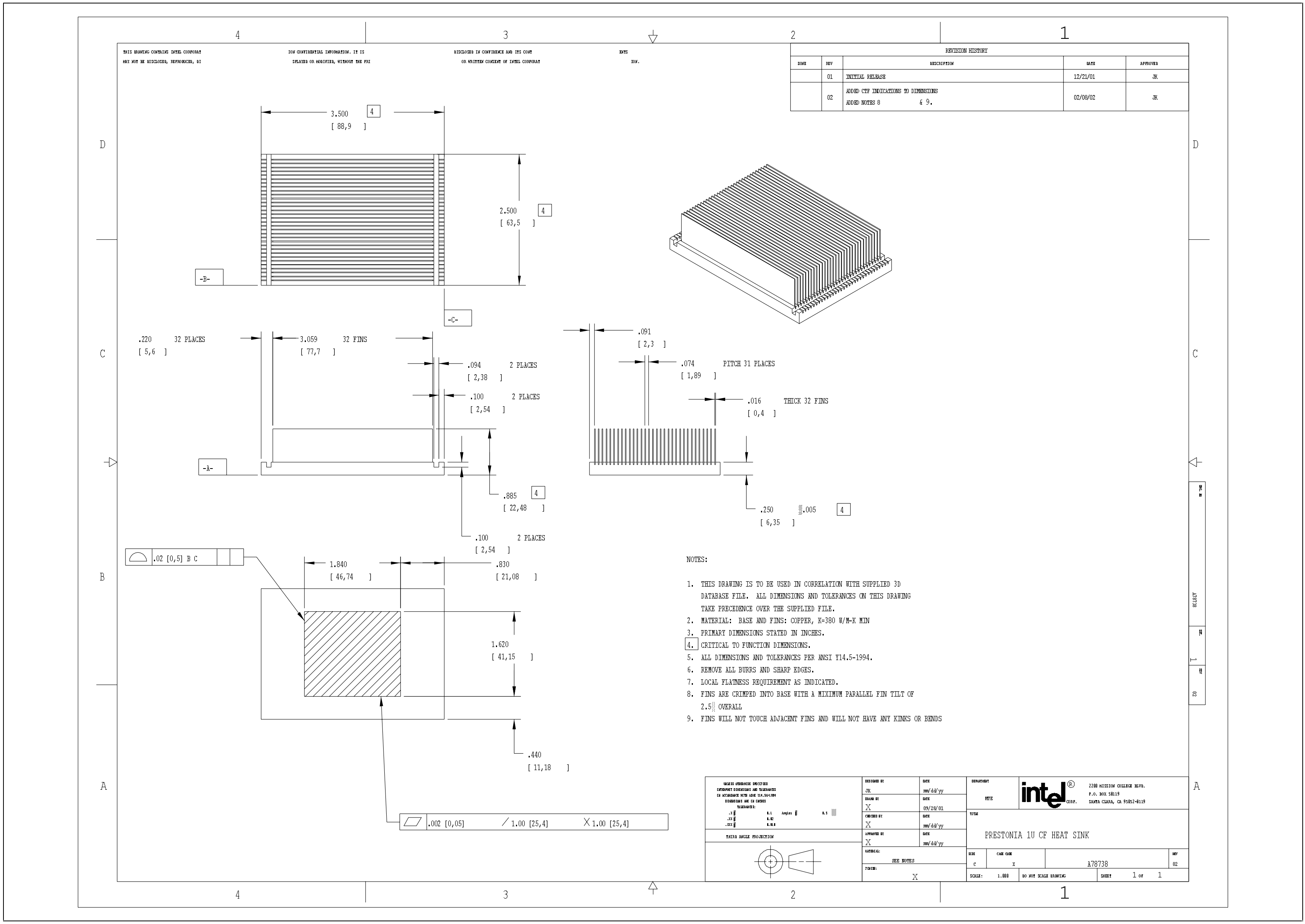


Figure 38. Intel® Xeon™ Processor with 512 KB L2 Cache Heatsink (1U)



NOTES:

1. THIS DRAWING IS TO BE USED IN CORRELATION WITH SUPPLIED 3D DATABASE FILE. ALL DIMENSIONS AND TOLERANCES ON THIS DRAWING TAKE PRECEDENCE OVER THE SUPPLIED FILE.
2. MATERIAL: BASE AND FINS: COPPER, K=380 W/M-K MIN
3. PRIMARY DIMENSIONS STATED IN INCHES.
4. CRITICAL TO FUNCTION DIMENSIONS.
5. ALL DIMENSIONS AND TOLERANCES PER ANSI Y14.5-1994.
6. REMOVE ALL BURRS AND SHARP EDGES.
7. LOCAL FLATNESS REQUIREMENT AS INDICATED.
8. FINS ARE CRIMPED INTO BASE WITH A MIXIMUM PARALLEL FIN TILT OF 2.5° OVERALL
9. FINS WILL NOT TOUCH ADJACENT FINS AND WILL NOT HAVE ANY KINKS OR BENDS

Figure 39. Intel® Xeon™ Processor with 512 KB L2 Cache Heatsink (1U) Bypass Gasket